

2021

**MCTR 701\_1**

# **Master Advanced Mechatronics**

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**Mechatronics  
common framework  
Lecture 2**

# Contents

## Lecture 2

### IMPLEMENTATION OF THE MECHATRONIC SYSTEMS RELIABILITY PREDICTION

#### PROCESS

- Implementation of a specific approach for mechatronic systems
- Application to the two industrial examples previously described

# Contents

- Objectives
- Issues
- Preliminary steps to the implementation of the approach
- Mechatronic system
- Bibliographic review (state of the art)
- Proposed approach: 10 steps
- Consolidation of the proposed approach
- Descriptions of the steps' approach and illustrations
- Conclusions
- Improvement areas

# Definitions

**Quality** = Conformance to specifications or requirements defined by customer at time  $t = 0$

Improvement of the quality can be improved by different methods and techniques:

- ISO 9004:2008
- Total Quality Management (TQM)
- Statistical
- Process control
- Six Sigma
- Quality Function Deployment (QFD)
- Quality Circle,
- Taguchi method
- ....

# Definitions

**Reliability** = ability of a system or component to perform its required functions under stated conditions for a specified period of time

# Definitions

**Maintainability** = ability of an item, under stated conditions of use, to be retained in, or restored to, a state in which it can perform its required functions, when maintenance is performed under stated conditions and using prescribed procedures and resources

- To reduce the chance of failures, **maintenance can be preventive or predictive**:
  - **Corrective Maintenance**: carried out after fault recognition to put an entity into a state in which it can perform a required function.
  - **Preventive Maintenance**: carried out at predetermined intervals or according to prescribed criteria and intended to reduce the probability of failure or the degradation of the functioning of an entity.
  - **Predictive Maintenance**: performed continuously or at intervals governed by observed condition to monitor, diagnose or trend a structure, system or components' condition indicators.

# Definitions

**Availability** = probability that a product or system is in operation at a specified time

The simplest representation of availability (A) is:

$$A = \frac{\text{Uptime of system}}{\text{Uptime of system} + \text{Downtime of system}}$$

Uptime depends on reliability of the system whereas downtime depends on maintainability of the system.

Thus availability is function of both reliability and maintainability.

# Definitions

**Failure** = is the opposite ability of reliability, it corresponds to the "cessation of the ability of an entity to perform a required function"

The faulty (failed) state corresponds to an unacceptable state (loss of function)

# Failures

**Failure** is inevitable for engineering systems.

## Impact of failures :

- minor inconvenience and costs
- personal injury
- significant economic loss
- environmental impact
- deaths

## Cause of failure :

- bad engineering design
- faulty manufacturing
- inadequate testing
- human error
- poor maintenance
- lack of protection against excessive stress



Fukushima  
Space X  
Chernobyl accident  
Bhopal gas tragedy  
space shuttle Columbia disaster



# Classification of failures

- Amplitude:
  - Partial, complete or total
- Speed of manifestation:
  - Progressive, sudden
- Amplitude and speed of manifestation:
  - By degradation, catalectic
- Date of appearance:
  - Early or youth, random or mature, aging
- Causes:
  - First, second, by control
- Effects:
  - Minor, significant, critical, catastrophic

# Need for Reliability and Safety Engineering

**Reliability** deals with the failure concept

**Safety** deals with the consequences after the failure

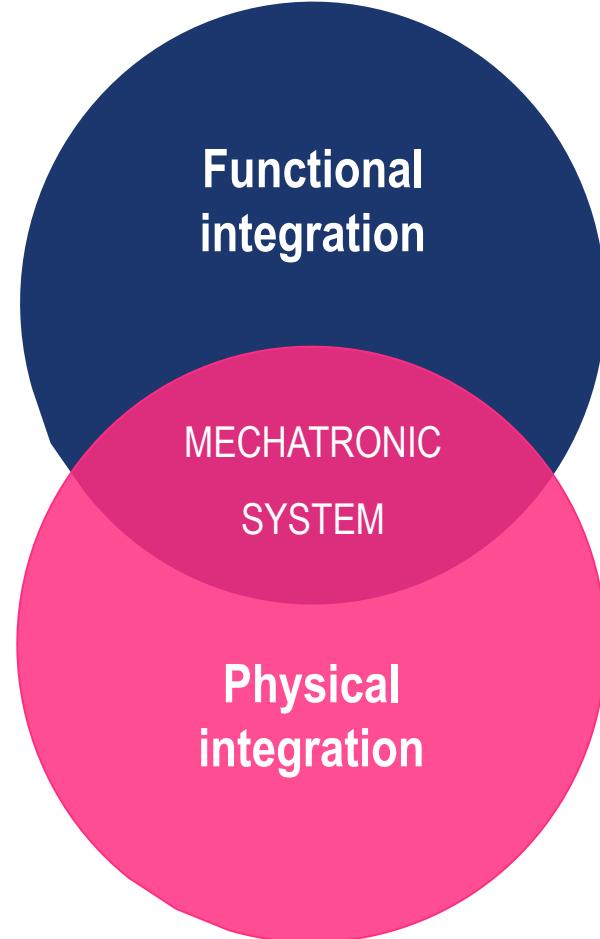
**It is essential :**

- to understand ‘why’ and ‘how’ failures occur to minimize them
- to know how often such failures may occur

**Reliability and safety engineering are improved by the following factors:**

- Design evaluation;
- Identification of critical components/events;
- Redundancy requirements;
- Burn-In/Accelerated life tests
- Establishment of preventive maintenance programs;
- Life cycle cost analysis

# Issues



Mechatronics

multiple technologies

- Reliability is traditionally studied by technology
  - partitioning and analysis by technical department (electronics, mechanics, software ...)
- Reliability is studied phase by phase\_(design, manufacturing,...)
  - *numerous dedicated methods exist with drawbacks, advantages and limitations*

Need for a interdisciplinary  
and overall approach

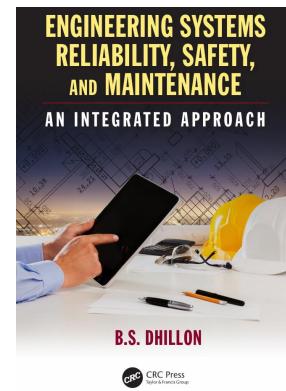
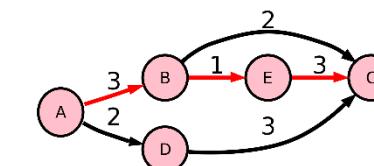
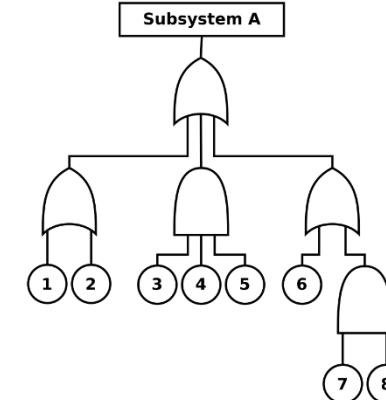
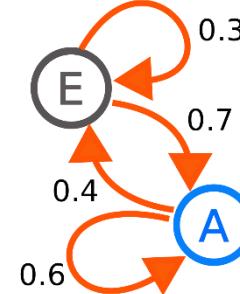
# Objectives of reliability prediction of mechatronic systems

To propose an approach able to estimate the predictive reliability of a mechatronic system during the design phase, that can take into account:

- the **intrinsic characteristics** of mechatronic systems
- the different **components and functions** of the system
- the **relations** between these components and functions
- the **mission profile**

# Methods for performing Reliability, Safety, and Maintenance Analysis

- Markov
- FTA (*Fault Tree Analysis*)
- TOR (*Technique of Operation Review*)
- **FMEA (*Failure Mode Effect Analysis*)**



# Bibliographic review / State of the art

Identification and analysis of the **state of the art** of the different **approaches** to study the reliability of mechatronic systems



Identification and analysis of the **deficiencies and gaps** in terms of reliability estimation for mechatronic systems

Keywords	Ziegler 1996	Moncelet 1998	Khalfaoui 2003	Schoenig 2004	Mihalache 2007	Demri 2009
reliability	-	-	-	-	+	+
mechatronic system	-	+	+	+	+	+
modeling	+	+	+	+	+	+
simulation	-	+	-	+	+	+
interdisciplinary dimension	-	-	-	-	-	-
vertical dimension	-	-	-	-	+	-
qualitative study	-	+	+	-	-	+
quantitative study	+	+	-	+	+	+
technological interdependences	-	-	-	-	-	-

- Neither **different functioning phases**, nor the **mission profile** and the **influent factors** are taken into account
- The **physical and functional interactions** created between the different technological parts are not studied
- No estimation of the **global reliability**

# An innovative approach designed at SYMME lab - USMB



Contents lists available at [ScienceDirect](#)

## Reliability Engineering and System Safety

journal homepage: [www.elsevier.com/locate/reess](http://www.elsevier.com/locate/reess)



An overall methodology for reliability prediction of mechatronic systems design with industrial application

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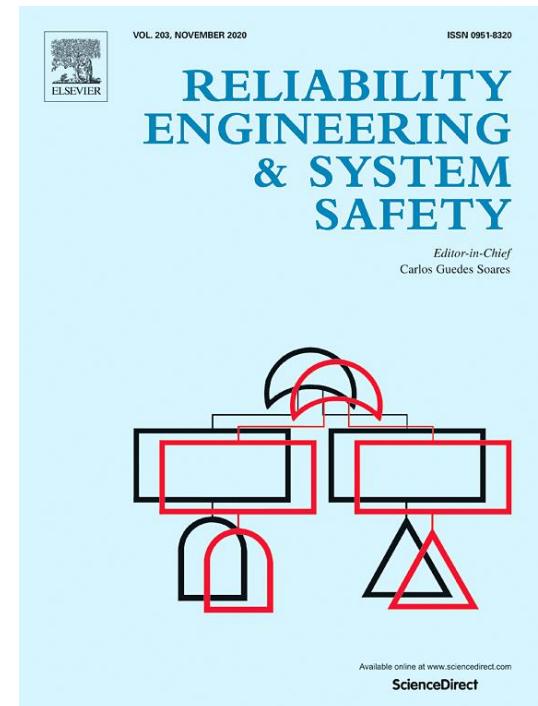
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Reliability  
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Dependencies  
Interactions  
Modeling  
Simulation

### ABSTRACT

We propose in this paper an overall ten-step methodology dedicated to the analysis and quantification of reliability during the design phase of a mechatronic system, considered as a complex system. The ten steps of the methodology are detailed according to the downward side of the V-development cycle usually used for the design of complex systems. Two main phases of analysis are complementary and cover the ten steps, qualitative analysis and quantitative analysis. The qualitative phase proposes to analyze the functional and dysfunctional behavior of the system and then determine its different failure modes and degradation states, based on external and internal functional analysis, organic and physical implementation, and dependencies between components, with consideration of customer specifications and mission profile. The quantitative phase is used to calculate the reliability of the system and its components, based on the qualitative behavior patterns, and considering data gathering and processing and reliability targets. Systemic approach is used to calculate the reliability of the system taking into account: the different technologies of a mechatronic system (mechanics, electronics, electrical ...), dependencies and interactions between components and external influencing factors. To validate the methodology, the ten steps are applied to an industrial system, the smart actuator of Pack'Aero Company.

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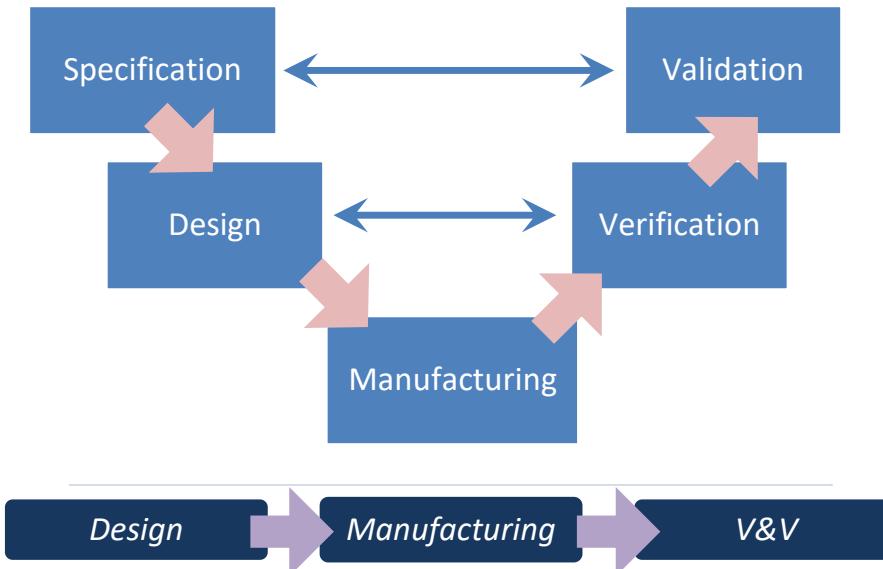


SYMME

# Proposed approach: initial considerations

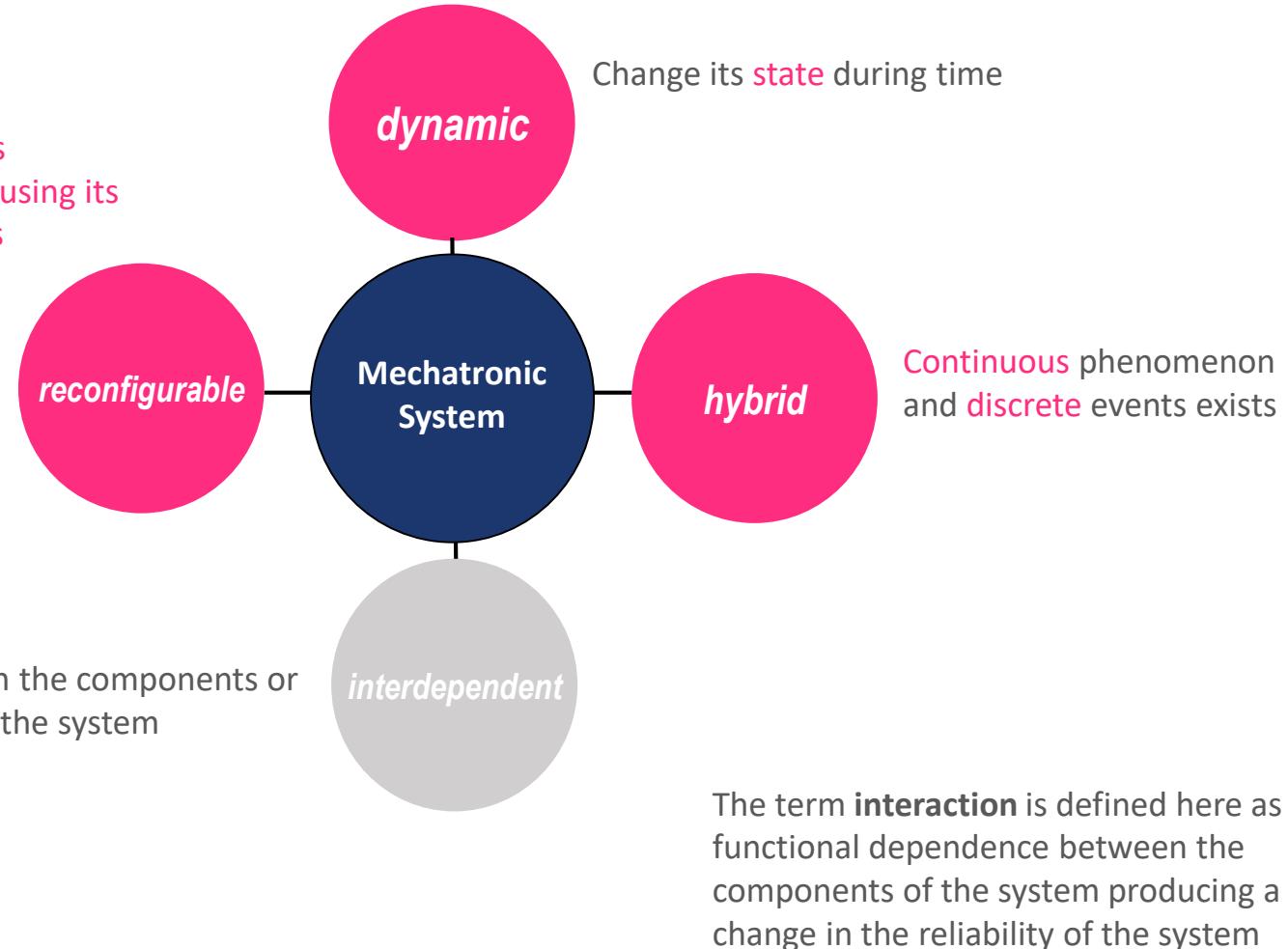
# Development model

- Based on the V- cycle
  - Interdisciplinary and overall approach
  - Qualitative and quantitative analysis
  - Intrinsic characteristics taken into account at each step
  - Under a defined mission profile
  - Interactions considered



# Proposed approach: initial considerations

Assume **different functions**  
alternatively or a **function using its  
resources in different ways**



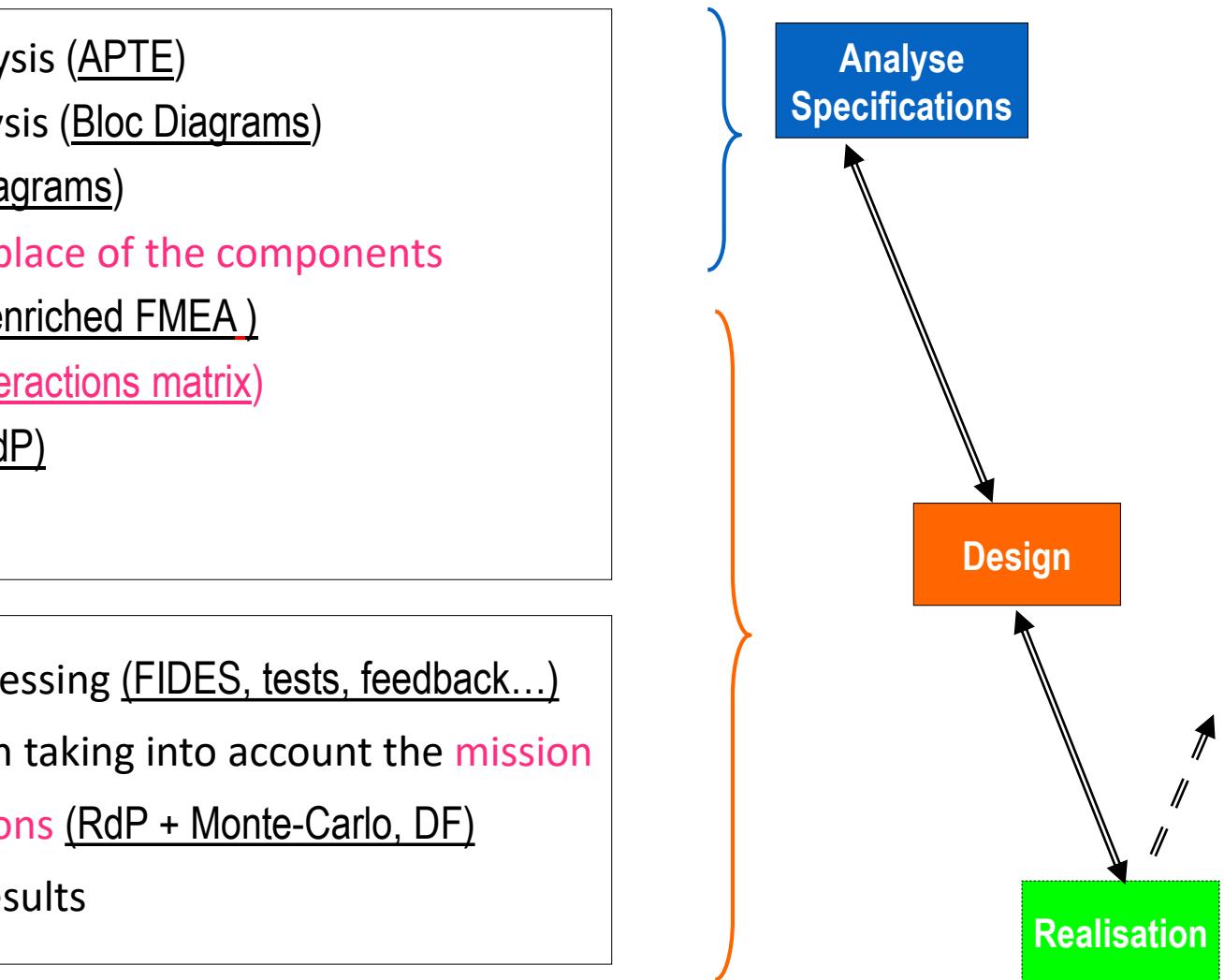
# Proposed approach: 10 steps

Qualitative analysis



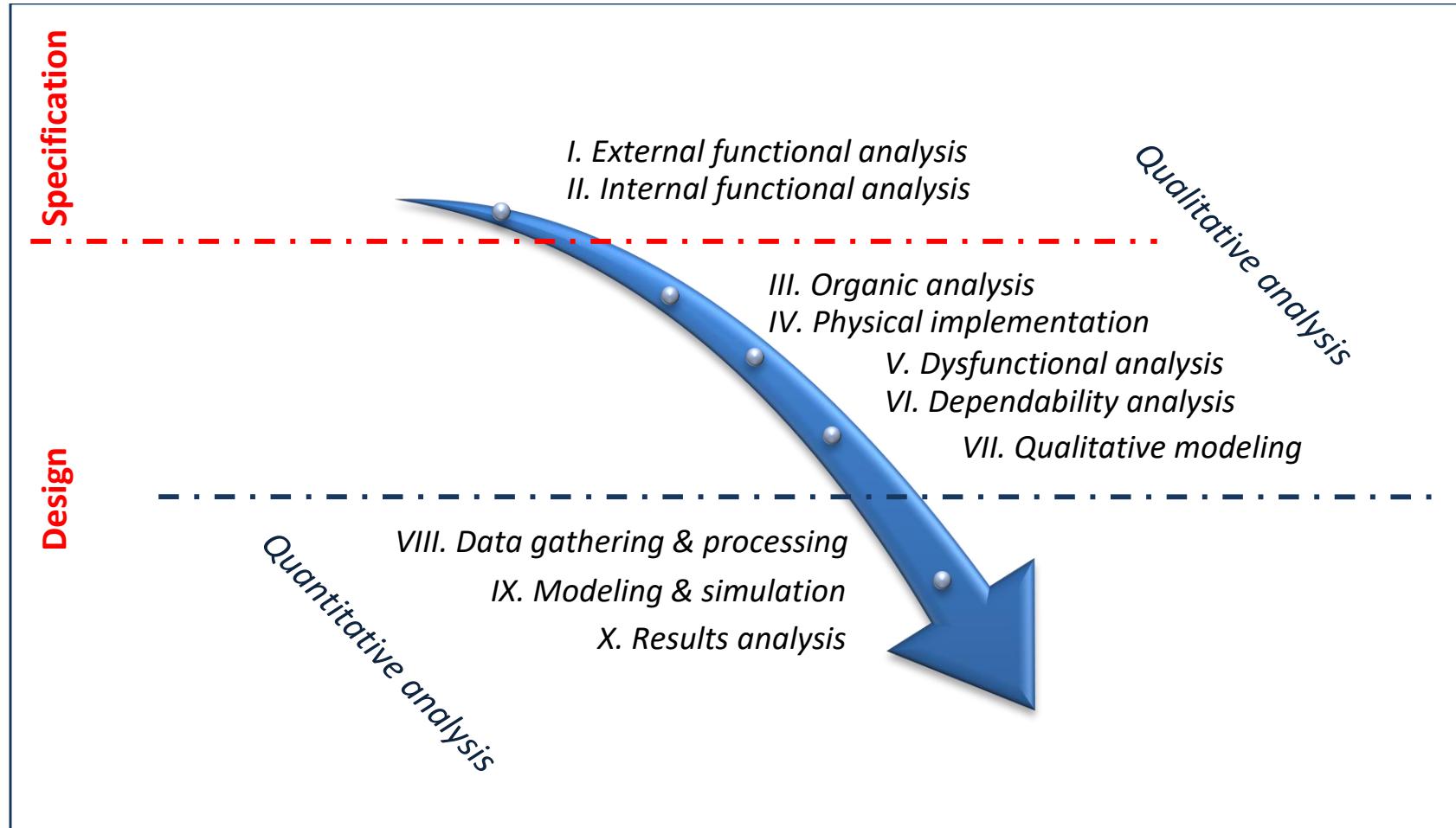
Quantitative analysis

1. External functional analysis (APTE)
2. Internal functional analysis (Bloc Diagrams)
3. Organic analysis (Bloc Diagrams)
4. Analysis of the physical place of the components
5. Dysfunctional analysis (enriched FMEA)
6. Interactions analysis (Interactions matrix)
7. Qualitative modeling (RdP)



8. Data gathering and processing (FIDES, tests, feedback...)
9. Modeling and simulation taking into account the mission profile and the interactions (RdP + Monte-Carlo, DF)
10. Analysis of simulation results

# Proposed approach: 10 steps



# Preliminary steps to the implementation of the approach

- The estimation of forecast reliability needs to provide the following informations :
  - Complete specifications
  - Reliability objectives
  - **Reliability data** concerning the components of the system and that are not available in database



A strong involvement of the company is needed in the implementation of the approach

# Consolidation of the approach

## Examples of industrial systems

Choice of 2 examples in order to run through the approach to realise it and consolidate it:

- Simple mechatronic systems
- Principal data available
- Industrial experimented in reliability
- Geographic proximity



# *Example to illustrate*

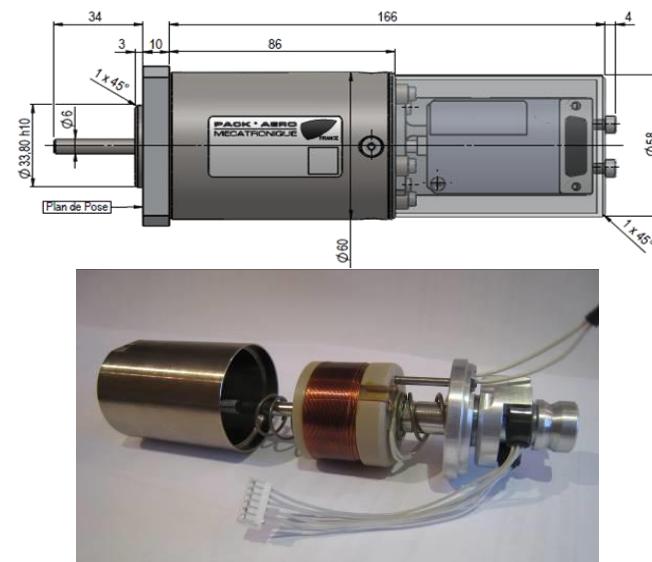
## Smart actuator



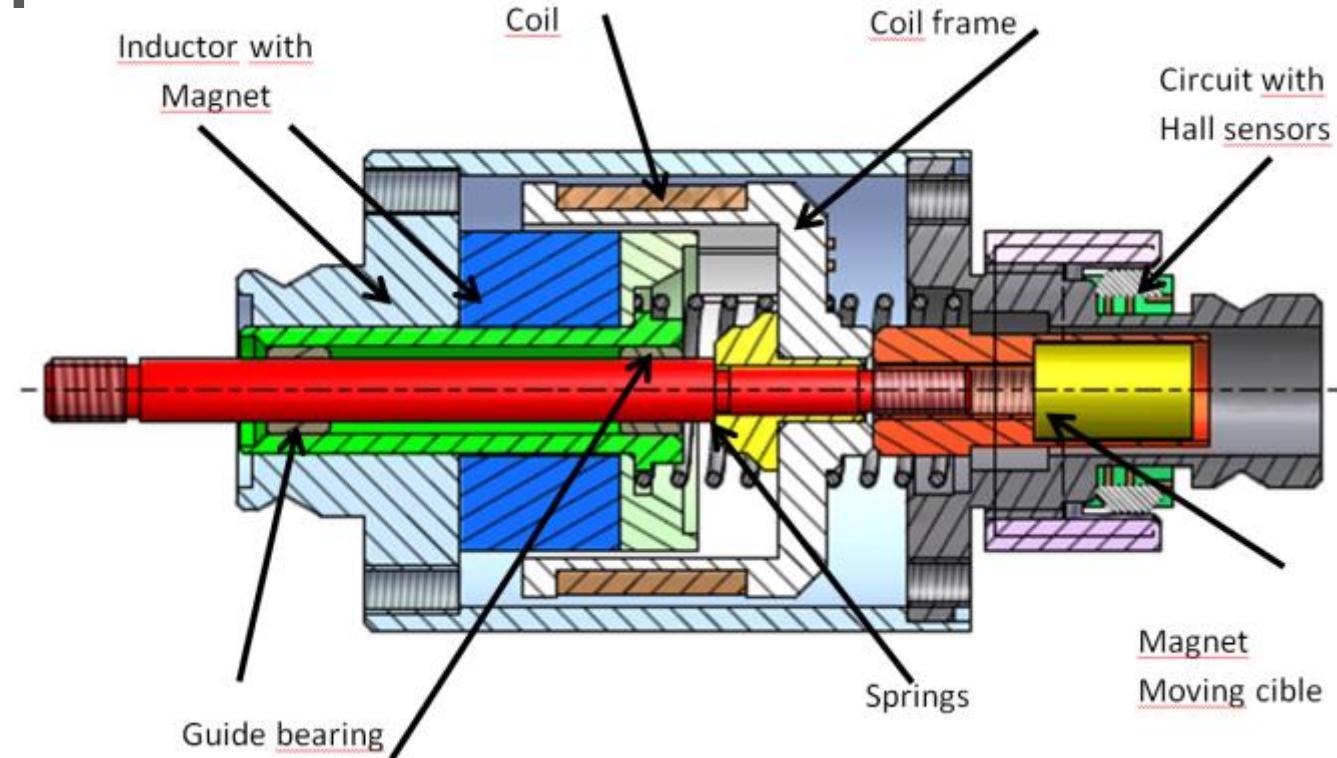
### ■ Specifications

In addition to be a classical actuator, the smart actuator assume additional functions such as operating, monitoring, communicating, data processing, etc.

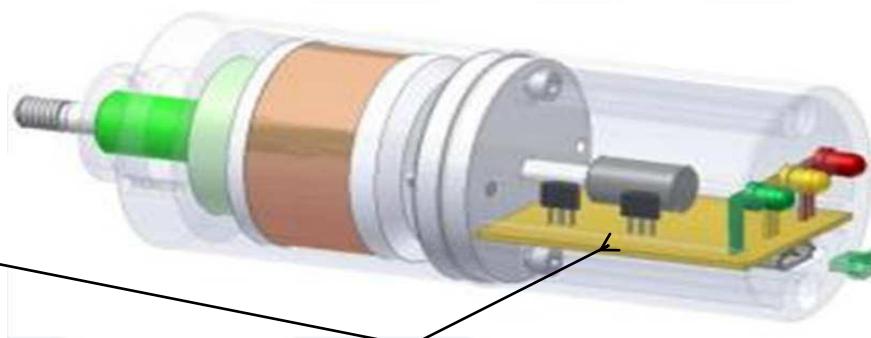
- > Transition from passive state to **active** state
- > Using a linear direct action instead of a linear indirect one
- > **Optimisation of the immediate answer** according to the needs
- > Integration of **electrical locking functions** with or without electricity consumption



# Overall plan



Physical implementation  
of the circuit board



# Example to illustrate

## ■ Using context

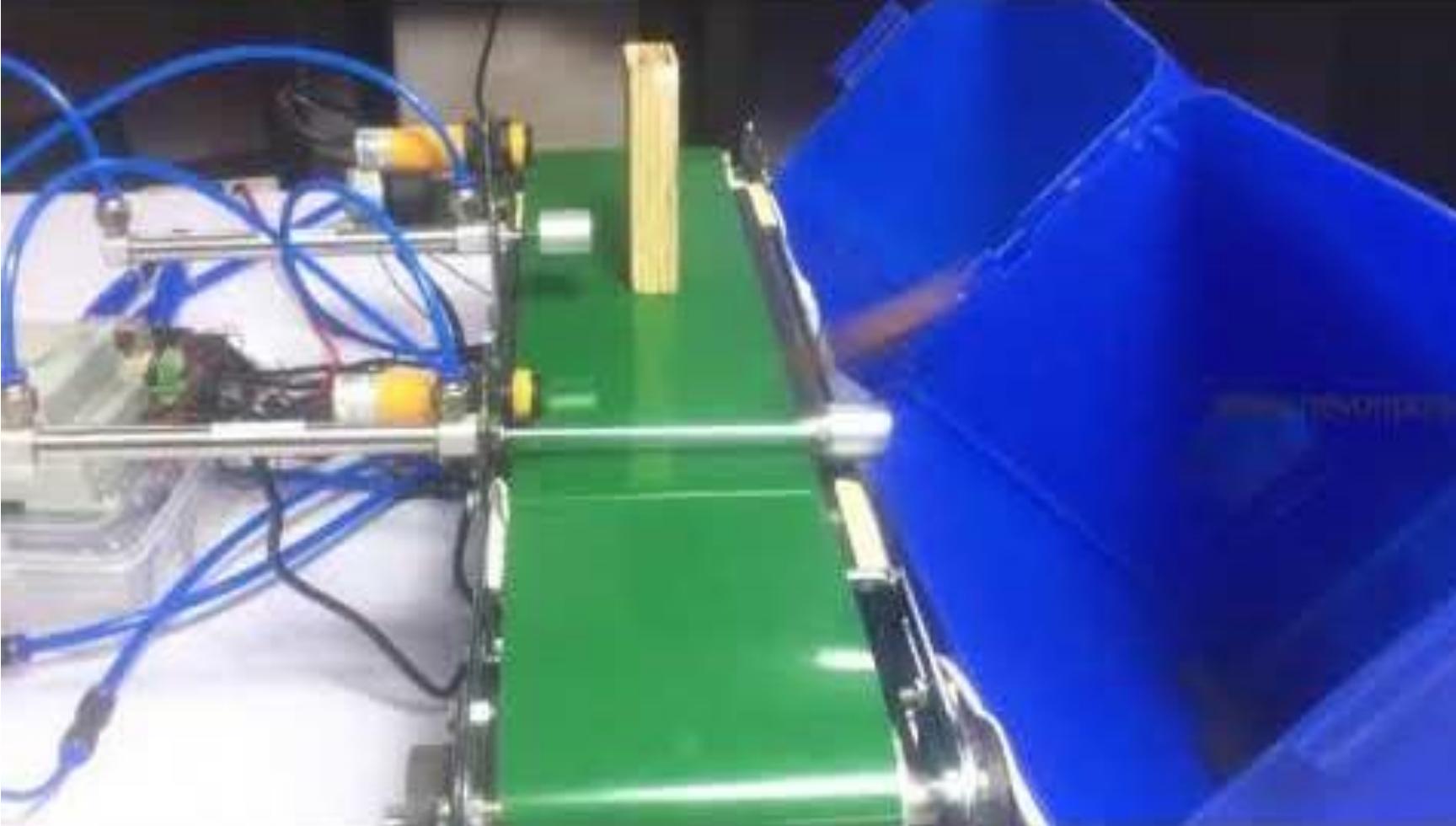
Continuous sorting line including 200 to 1000 wagons.

- The wagons carry parts from a station to another of the chain in continuous motion
- The actuator contributes to the realization of the function of wagons unloading

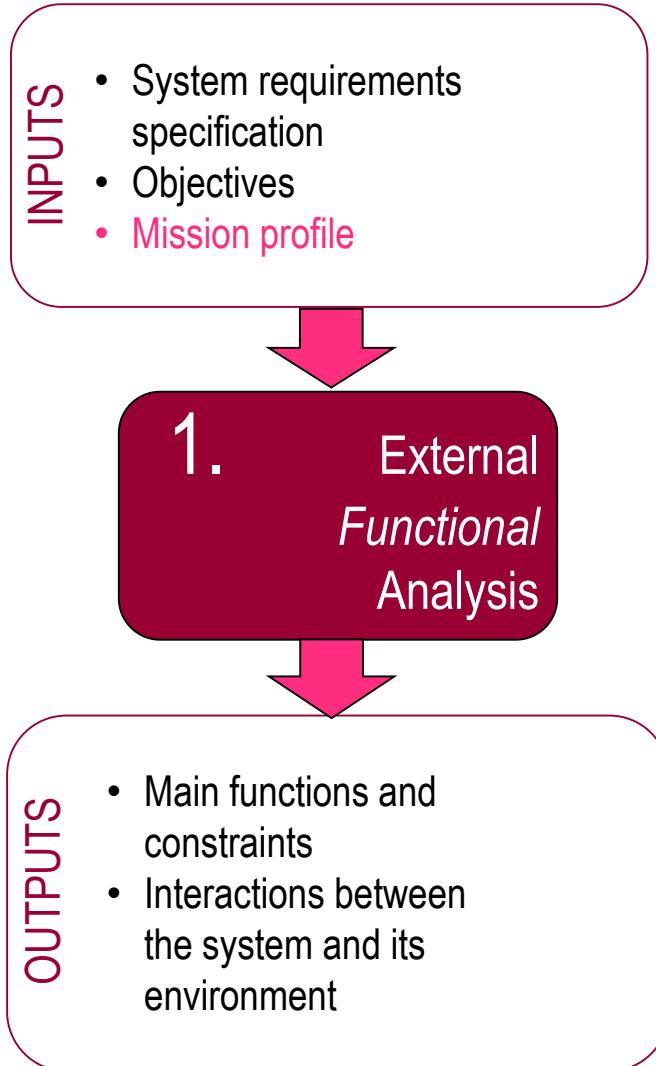
The finger of the smart actuator is used as a stop to open the shutter and release (let go) the load of wagon without stopping



## Example to illustrate



# 1. External functional analysis



Describes:

- The expected function for **each phasis of the profile**
  - The reactive functions to take into account the environment
  - The **constraints** imposed by the users
- To write the Functional Specification

## Mission profile

Component failure rates are very sensitive to the stresses applied.

Stresses, which can be classified as environmental or self-generated, include:

Temperature Shock Vibration Humidity Ingress of foreign bodies	Environmental
Power dissipation Applied voltage and current Self-generated vibration Wear	Self-generated

The intended use and environment of a system must be accurately stated in order to realistically measure Reliability.

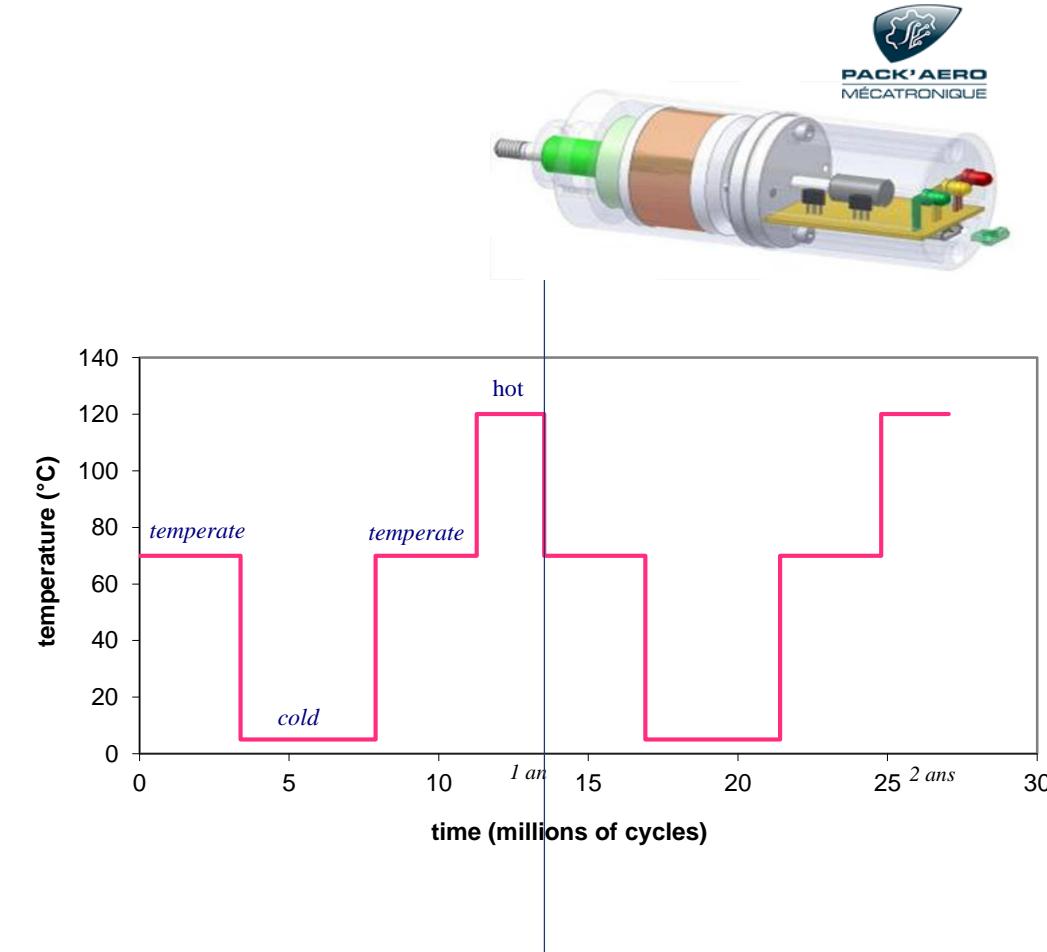
**Mission profiles** is an effective tool for that purpose

## Mission profile

- The mission profile will be taken into account in the estimation of the predictive reliability.

Example of a mission profile for the actuator

- An influent factor : temperature
- Three different functioning phases: cold, temperate, hot

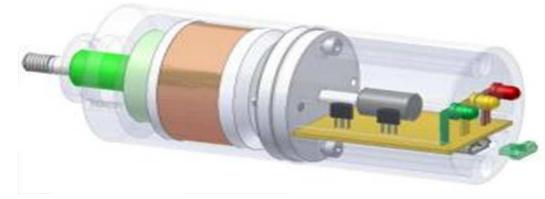
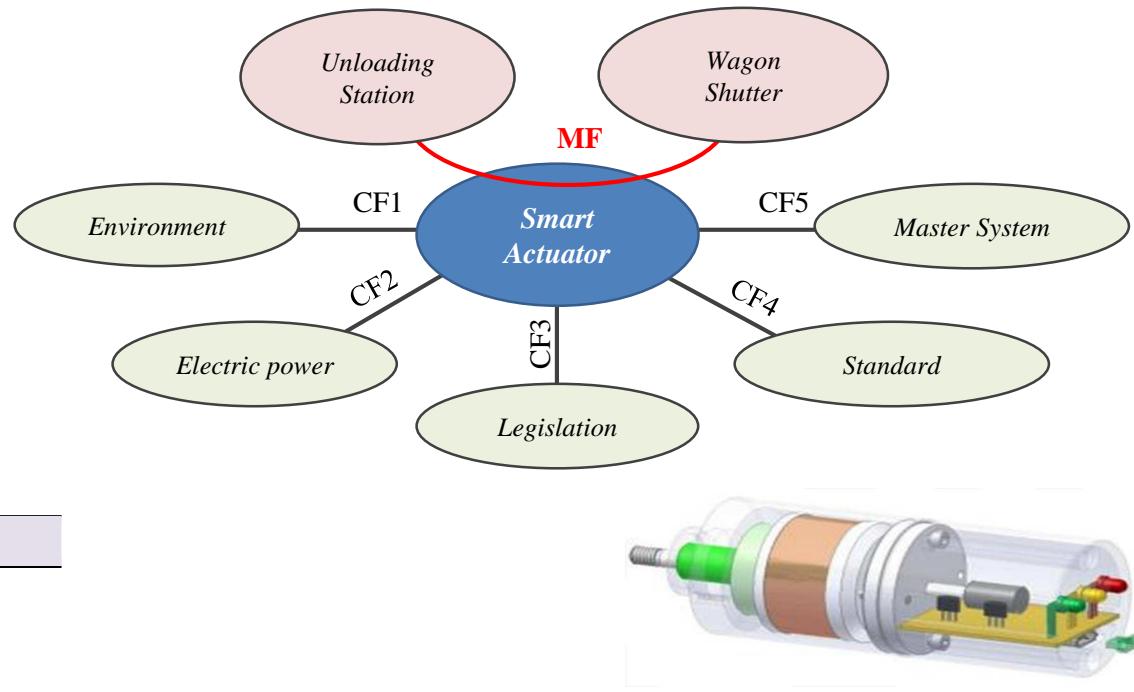


# Functional Specification

## APTE : Application of Corporation (Professional) Methods

### Characteristics of the main function and constraint functions

Function	Criteria/Target	Value/Information
	Average number of opening/closing cycles before the occurrence of a first failure (MTTF)	10 million of cycles
	Desired lifetime	10 years
<b>MF</b>	Operating information	Intermittent operation Electric power: 1 slot ON-OFF/60 ms Duration of an opening/closing cycle: 40 ms Time between two cycles: 1.67 s Operation time 20 h/24, 6 days/7
<b>CF1</b>	Temperature and duration of the hot phase	120°C for 2/12 of cycles
	Temperature and duration of the cold phase	5°C for 4/12 of cycles
	Temperature and duration of the temperate phase	70°C for 2 times 3/12 of cycles
<b>CF2</b>	Electric power and voltage	10 W and 24 V +/- 5%
<b>CF3</b>	Meet the legislation requirements	Low Voltage Directive: NSC 20-030 Directive clean machine (Example: Noise emitted by equipment NFEN 11201)
<b>CF4</b>	Meet the normative standard requirements	Degree of electrical protection: NFEN60529 Noise emitted by equipment: NFEN 11201
<b>CF5</b>	Working order Stop order	TOR function (1) TOR function (0)



**MF:** Allows wagon shutter opening when the wagon arrives at the unloading station,

**CF1:** Withstands the thermal environment,

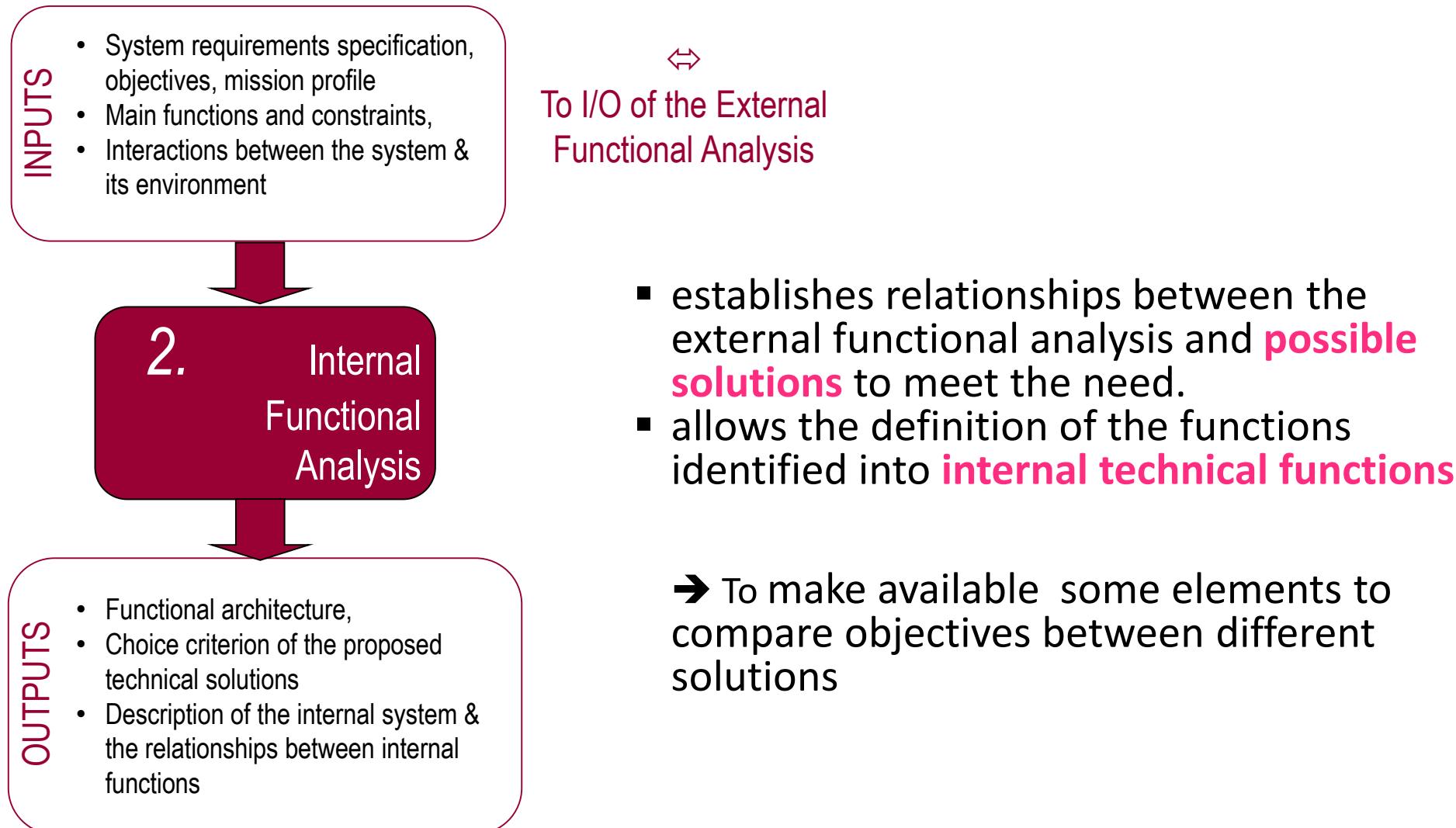
**CF2:** Works with the installed electrical power,

**CF3:** Meets the requirements of legislation,

**CF4:** Meets the normative standards requirements,

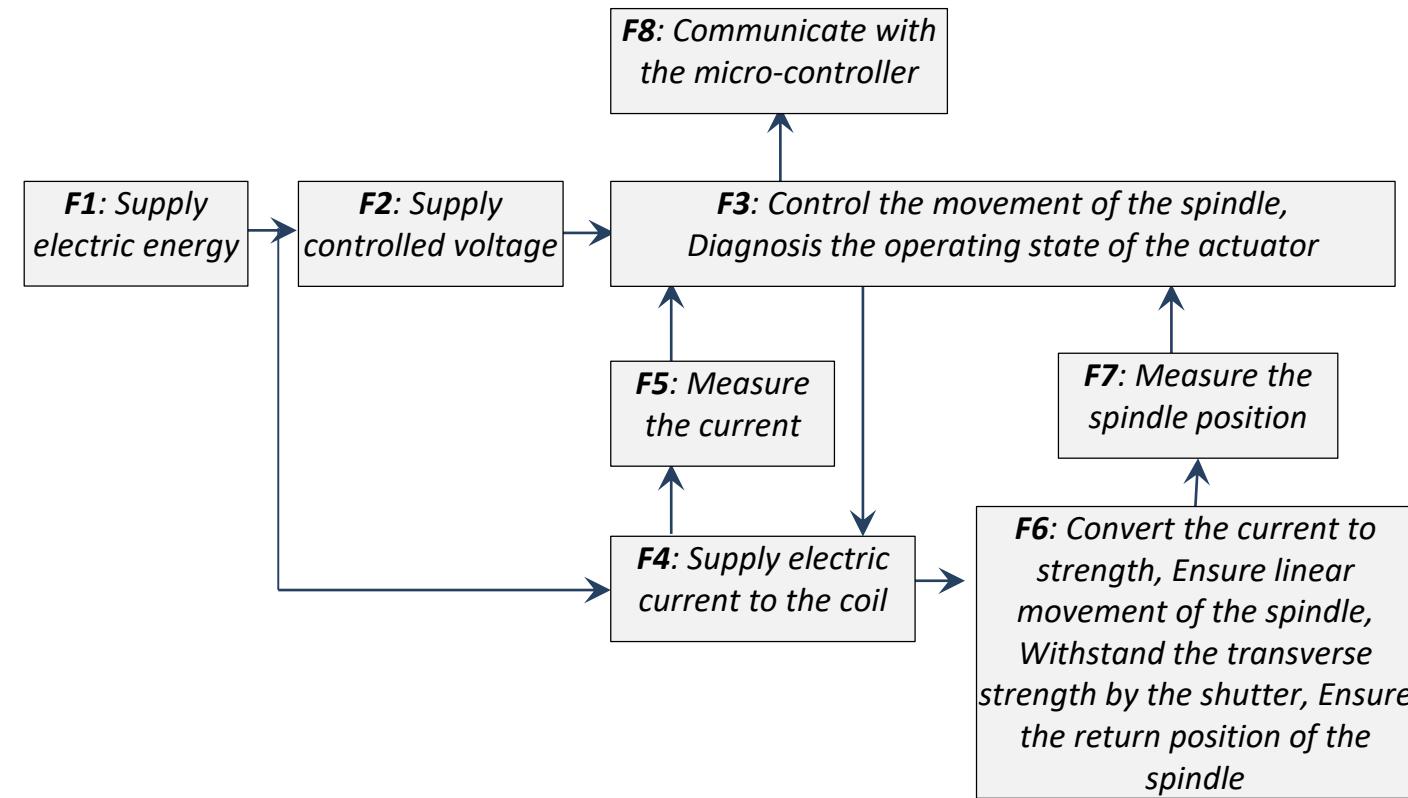
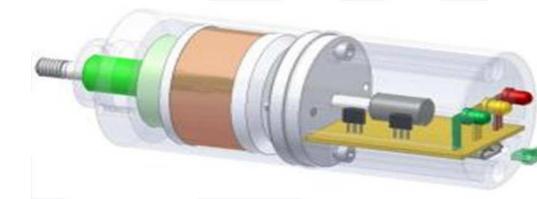
**CF5:** Allows the master system to order operating (ON/OFF).

## 2. Internal functional analysis

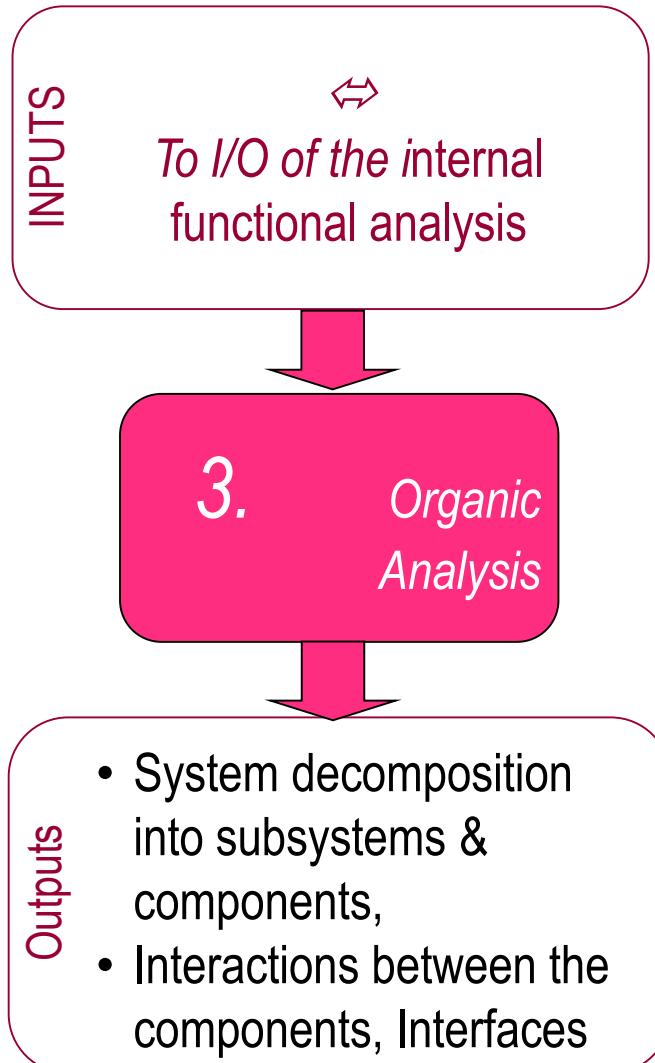


# Functional Block Diagram (FBD)

FBD is a tool used to map the key internal functions and the relationships between these functions.

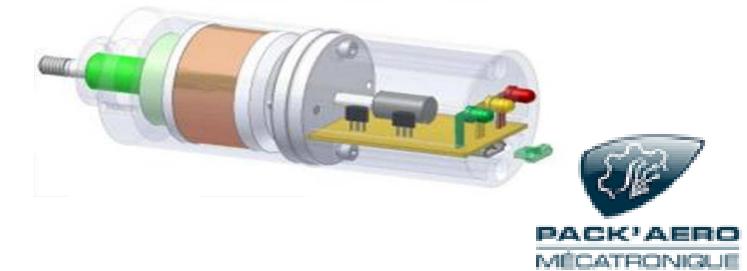
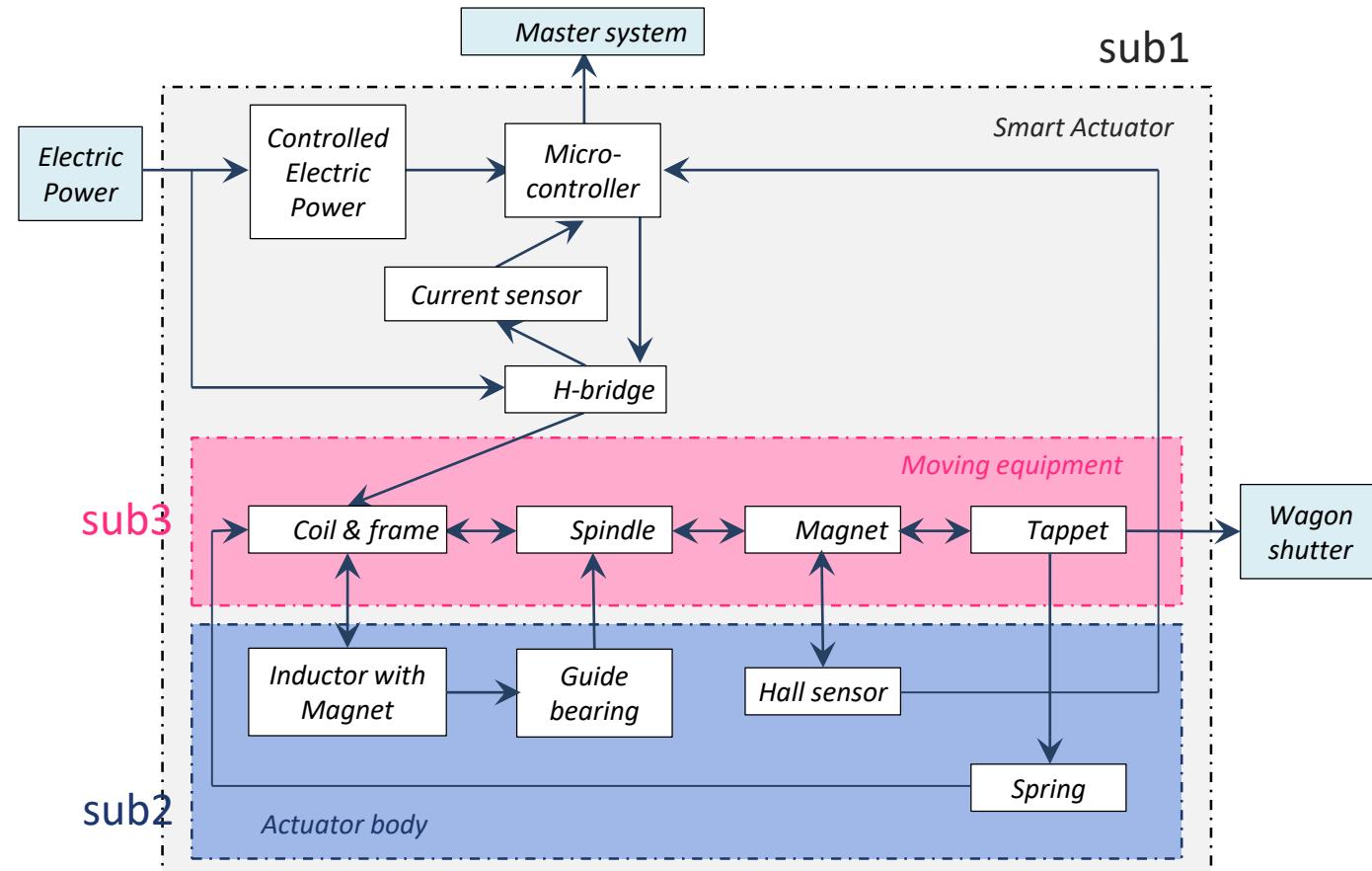


### 3. Organic Analysis



- Defines the **architecture of the system**, the decomposition into **sub-systems and components**
- Identifies the **functional interactions** between the different elements of the system to fit with the expected functions

# Organic system architecture



3 sub-systems:

- Sub1= electrodynamic linear actuator with a mobile coil
- Sub2= contactless displacement sensor combining Hall probes and a mobile magnet
- Sub3= conditioning circuit board

## 4. Physical Implementation

- INPUTS
- Sub-systems
  - Components
  - Interactions
  - Interfaces

### 4. Physical implementation

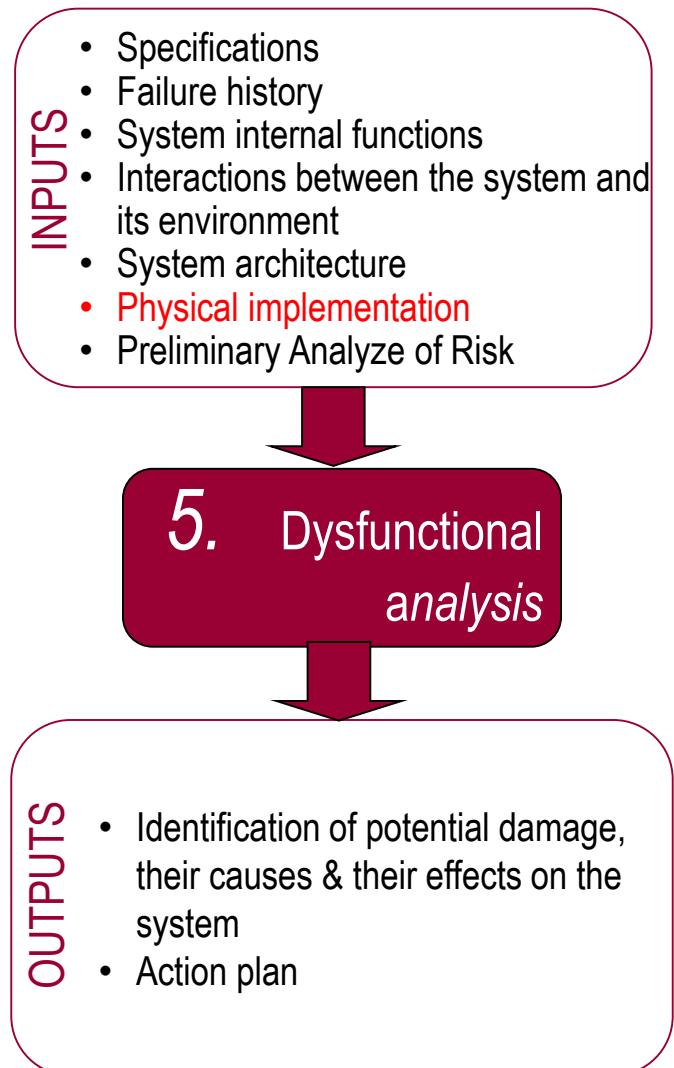
Supplementary step proposed compared to a conventional design approach

- Optimises the **locations** of the parts or organs
- Highlights the **physical proximity** of components

→ To minimise the collateral interactions' effects on the reliability of the system

- OUTPUTS
- Overall plan of the system
  - Collateral interactions identification

# 5. Dysfunctional Analysis



- Identifies failure modes and rank them according to their effects on the product performance:
  - > **Intrinsic** failures
  - > **Functional** failures identified thanks to the organic architecture
  - > **Collateral** failure issued from the physical implementation analysis
- FMEA (Failure Modes and Effects Analysis) → **inductive** approach to analyze the failure modes and their effects to order them (according to their criticity) to master them.

# *FMEA (Failure Mode Effect Analysis)*

- FMEA is a widely used method for analyzing the reliability of engineering systems
- It involves studying a circuit or mechanical assembly to decide how its component parts contribute to the overall failure mode in question.
- The method consists of assessing the effect of each component part failing in each possible mode.
  - Step 1: Define system boundaries and its associated requirements.
  - Step 2: List system subsystems and components.
  - Step 3: List each component's failure modes, the description, and the identification.
  - Step 4: Assign failure occurrence probability/rate to each component failure mode.
  - Step 5: List each failure mode effect/effects on subsystem(s), system, and plant.
  - Step 6: Enter necessary remarks for each failure mode.
  - Step 7: Review each critical failure mode and take necessary actions.

# *FMEA (Failure Mode Effect Analysis)*

- **Description**
  - describes inherent causes of **events** that lead to system failure,
  - determines their **consequences**
  - formulates methods to minimize their occurrence or recurrence.
  - allows identifying the **critical** elements of security and dormant faults.
- **Advantages**
  - **Simple** approach
  - Large application domains: design and exploitation
  - Analysis table giving a good **traceability** and **decision support**
- **Drawbacks / limitations**
  - Considered only one failure at a time
  - Limited insight into the functional relationships between components,
  - Time element in system operation cannot be represented.
  - Limited insight into probabilistic system behavior,
  - Better-adapted for mechanical or analog systems than digital ones

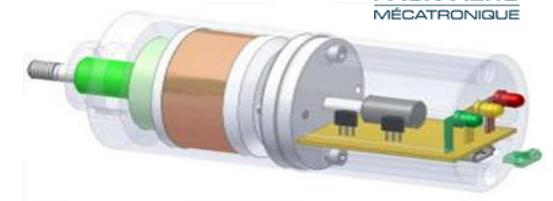
# FMEA (*Failure Mode Effect Analysis*)

## Enriched method

Classification of the failures **according the damage's origin**

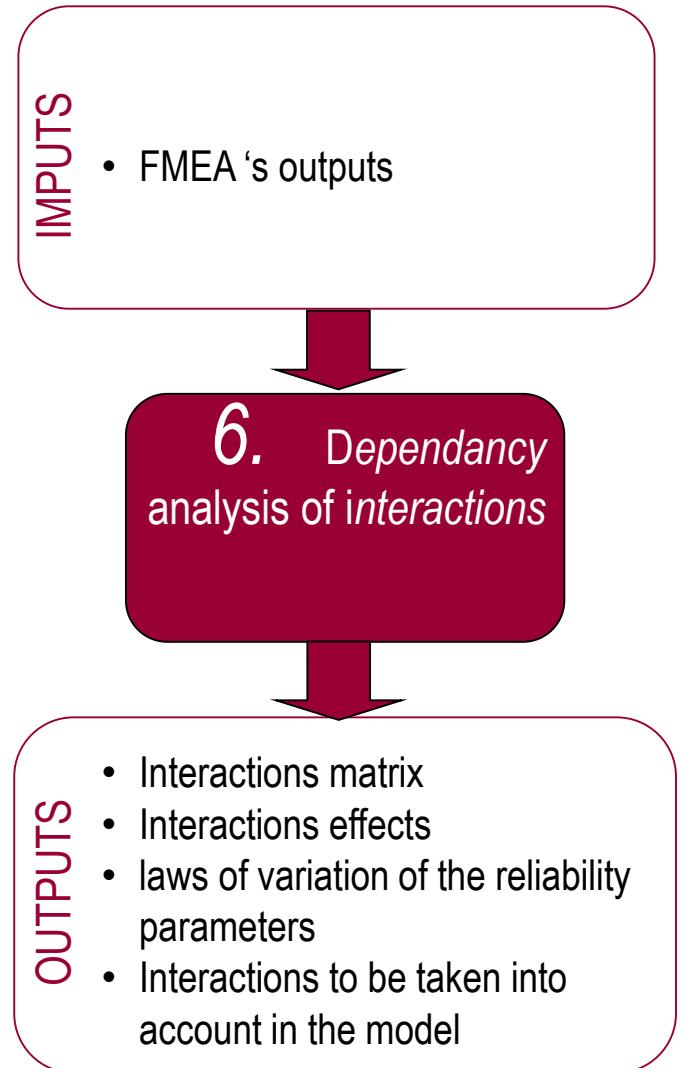
(intrinsic, collateral, and functional) and giving:

- its nature (first or second or by command)
- its event speed (sudden or progressive)
- its amplitude (partial or complete)



<u>Sub-system</u>	<u>component</u>	<u>Function</u>	<u>Failure mode</u>	<u>Cause</u>	<u>Effects</u>	<u>Damage's origin</u>	<u>Classification : nature / event speed / amplitude</u>
mobile	Coil + frame	F6	<ul style="list-style-type: none"> <li>- Swelling of the cuivre wire [8].</li> <li>- Swelling of the frame</li> <li>- Breakdown of the material</li> <li>- Breakdown of the wire [8]</li> <li>- Wrong value of the current on the coil</li> <li>- Wrong position of the frame</li> </ul>	Thermal heating, vibration, impact	No opening of the shutter	Collateral	Second, progressive, partial
				Excessive pressure or excessive translation speed	No opening of the shutter	Collateral	Second, progressive, partial
				Material fatigue [8]	No opening of the shutter	Intrinsic	First, progressive, complete
				Damage of inductor with magnet	No opening of the shutter	Fonctional ( <i>Inductor → Coil</i> )	First, sudden, complete
				Damage of H Bridge	No opening of the shutter	Fonctional ( <i>H-Bridge → Coil</i> )	First, sudden, complete
				Decentering of the rod	No opening of the shutter	Fonctional ( <i>Rod → coil frame</i> )	First, sudden, complete

# 6. Dependency analysis of interactions



Additional analysis compared to a conventional design approach

- Identifies interactions defined and classified in the **enriched FMEA** (a criticality analysis will be necessary).
- Allows to make the **choice of the interactions to be considered** in modeling the system in terms of reliability.

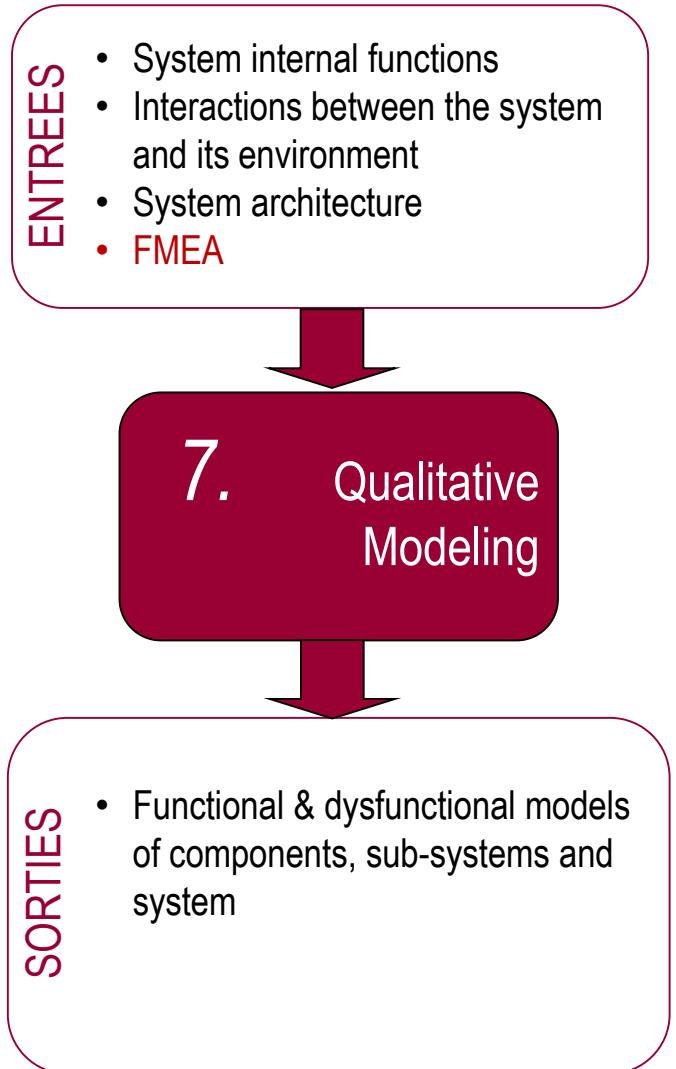
# Interactions matrix

Acts on		Subsystem 1			Subsystem 2		
		Comp 1	Comp 2	Comp 3	Comp <i>i</i>	Comp <i>k</i>	Comp <i>n</i>
Subsystem 1	Comp 1	UF		BF			
	Comp 2						
	Comp 3						
Subsystem 2	Comp <i>i</i>					UC	
	Comp <i>k</i>	BC		UF			
	Comp <i>n</i>						

**UF** for unidirectional functional interaction  
**BF** for bidirectional functional interaction  
**UC** for unidirectional collateral interaction  
**BC** for bidirectional collateral interaction

- Power supply acts on controlled power and on H-bridge,
- Controlled power acts on micro-controller,
- H-bridge acts on current sensor and on coil,
- Micro-controller acts on H-bridge and on master system,
- Current sensor acts on micro-controller,
- Coil acts on shutter,
- Magnet acts on tappet and on Hall sensor,
- Coil acts on inductor & magnet / inductor & magnet acts on coil,
- Magnet acts on shutter / Shutter acts on magnet.

# 7. Qualitative Modeling

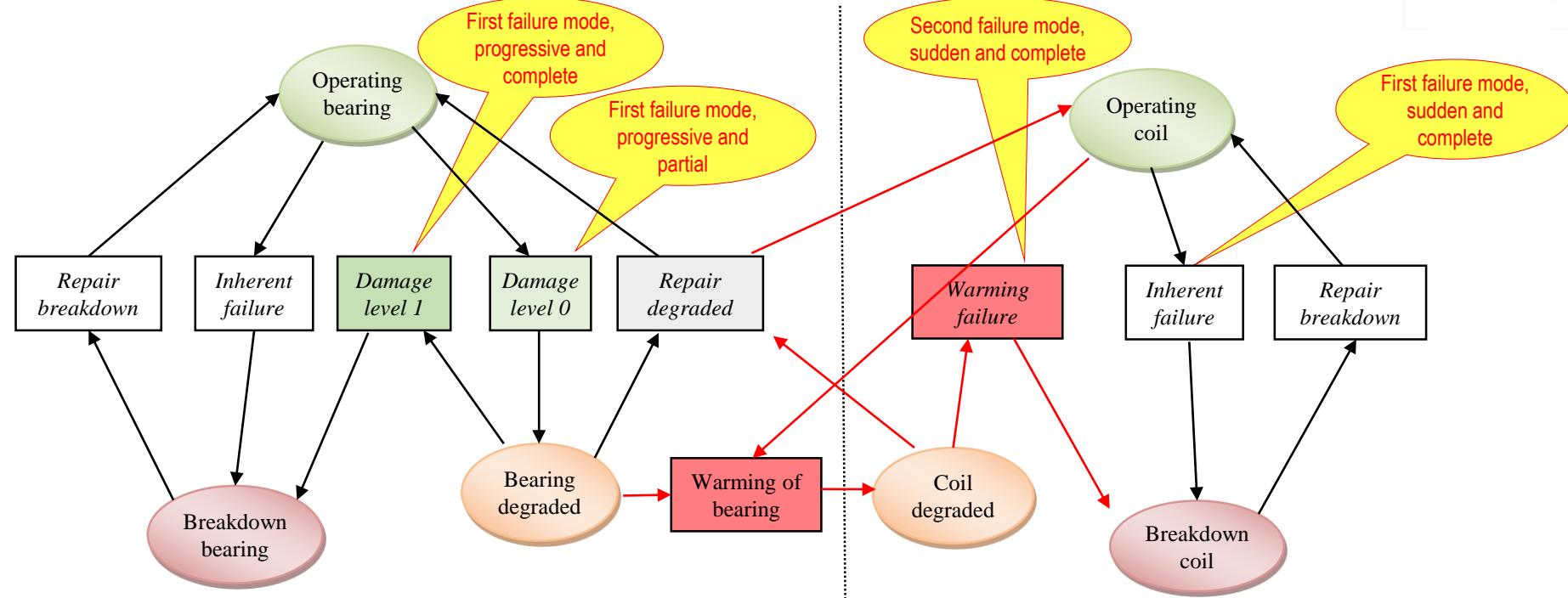
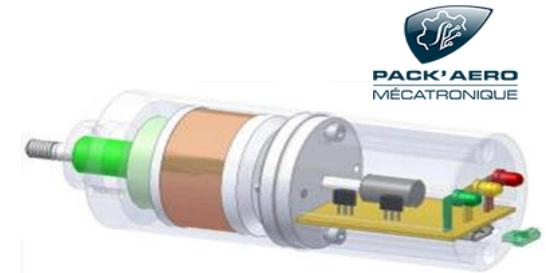


**Models the functional and dysfunctional behavior of the system and its components, taking into account the interactions**

- **States:** idle, operating, breakdown (whatever the mission profile phase), repair and degraded,
- **Transitions between states:** failure modes, events, repair modes

## 7. Qualitative modeling

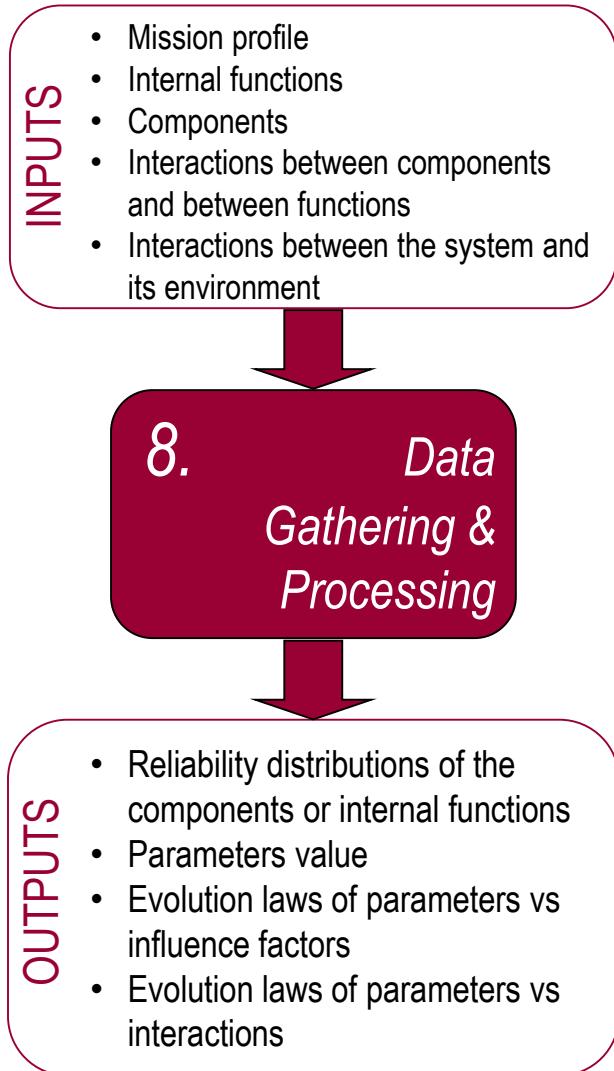
- Modeling of both components: guide bearing / coil
  - Bearing wear
  - Collateral interaction linked to the physical implementation guide bearing / coil



- Interactions modeled by implemented new states and modes:

- > 5 states for each component: idle, operating, breakdown, repair and **degraded**
- > 3 failure modes for the bearing, 2 failure modes for the coil
- > 2 repair modes for the bearing, 1 repair mode for the coil

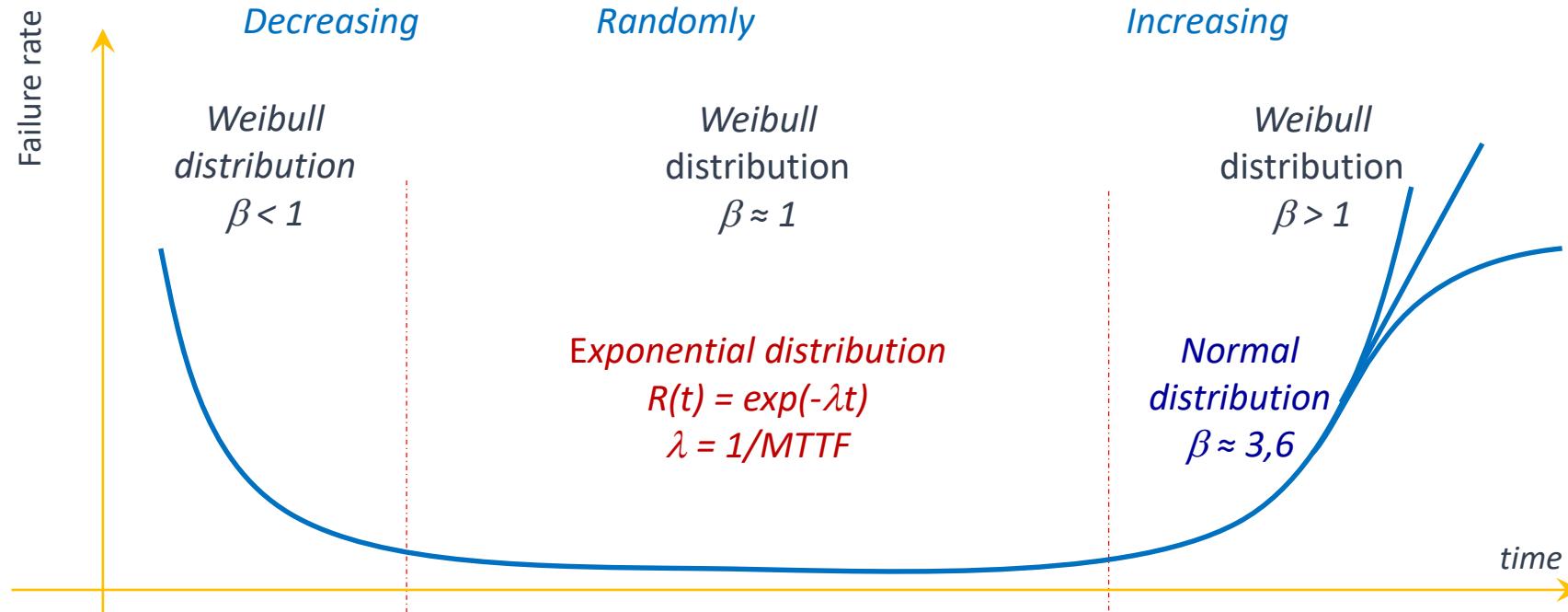
# 8. Components Data Gathering & Processing



Consists to :

- **Gather the reliability** data available on components (database, experiment, simulation, expertise...)
- **Process the data** (statistic analysis, influence of influential factors, influence of interactions...)
- **Identify relevant distributions** of reliability and the associated parameters for each component

# Reliability distribution and parameters



*Exponential distribution*  
 $R(t) = \exp(-\lambda t)$   
 $\lambda = 1/\text{MTTF}$

$$\text{Weibull Distribution : } R(t) = \exp \left[ - \left( \frac{t-\gamma}{\eta} \right)^\beta \right]$$

$\beta$ : shape parameter ;  $\eta$ : scale parameter ;  $\gamma$ : position parameter

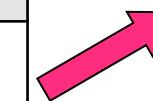
# Reliability distribution and parameters

Technology	Comments	Reliability distribution and parameters
Electronics	Known distribution and parameters available in Database	Exponential : <b>MTTF*</b> or $\lambda$ (failure rate)
Mechanics	<ul style="list-style-type: none"><li>Distribution are known for few standard elements</li><li>To find for most of specific components</li></ul>	Weibull : <ul style="list-style-type: none"><li><math>\beta</math> (shape parameter)</li><li><math>\eta</math> (scale parameter)</li></ul>

\*MTTF : Mean Time To Failure



FIDES 2009  
(reliability database for electronic components)

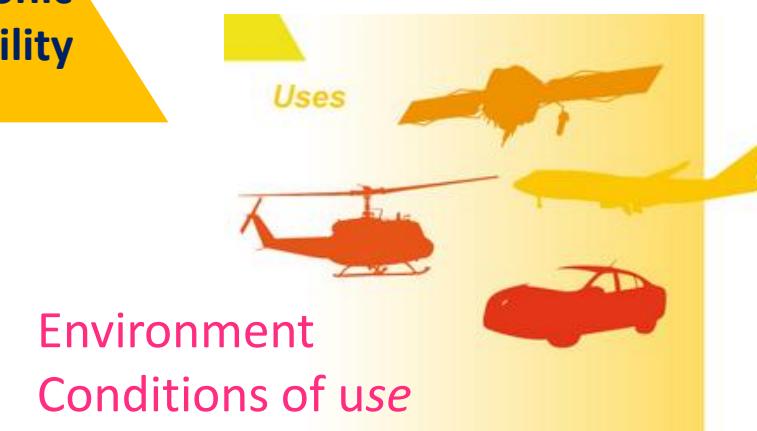
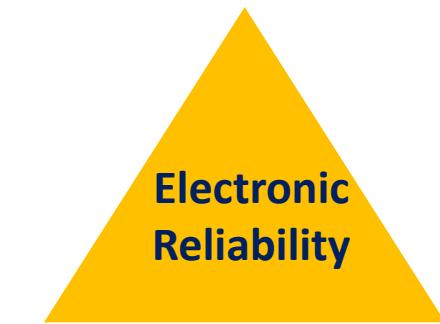


Feedback or estimation of reliability parameters for mechanical components

# FIDES database

The expression of the failure rate or the MTTF of electronic components depends on several factors that themselves depend on 3 steps:

- design technology
- manufacturing process
- environmental operation



# FIDES

- Objectives
  - To evaluate the **reliability parameters of electronic components** taking into account their using conditions (**exponential distribution**)
- Description
  - Developed, under the aegis of the DGA, by a consortium composed of AIRBUS, EUROCOPTER, NEXTER, MBDA and THALES
  - Includes failures relatives to specifications, design, manufacturing, except for software failures
  - Appropriate for components, electronic circuits or sub-systems (COTS - Commercial Off-The-Shelf)
- Relevant fields of study
  - All field using electronics

# FIDES

- Approach management
  - Calculation of the predicted failure rate  $\lambda = \lambda_{\text{physical}} \cdot \Pi_{\text{Part\_manufacturing}} \cdot \Pi_{\text{Process}}$
  - The factor **physical** takes into account the **mission profile** of the COTS
  - The factor  $\Pi_{\text{Part\_manufacturing}}$  reflects the **quality and technical control of component manufacturing or of COTS** (depends on its nature, from 0.5 to 2 worst case)
  - The factor  $\Pi_{\text{Process}}$  reflects the **quality and technical control of the processes of developing, manufacturing and use of products** containing the COTS (evaluated thanks to an audit, from 1 to 8 worst case)
- Inputs
  - Mission profile information (phases, duration, temperature, humidity, vibration, etc..), life profile, environment and using conditions
  - Data concerning : suppliers of the used components, equipment definition, life cycle
- Outputs
  - Predicted failure rate or MTTF

# FIDES

- Advantages
  - Takes into accounts the whole mission profile :
    - Phases and using cycles
    - Some influent factors
  - Include the complete product failures
- Drawbacks
  - The quality results depends on those of the different multiplying factors  $\Pi$
  - Particular care for the audits used to quantify the quality Process
- References
  - FIDES Guide available on the Web :  
<http://www.fides-reliability.org>

# Taking into account the influent factors of the mission profile on FIDES

Two influent factors considered:

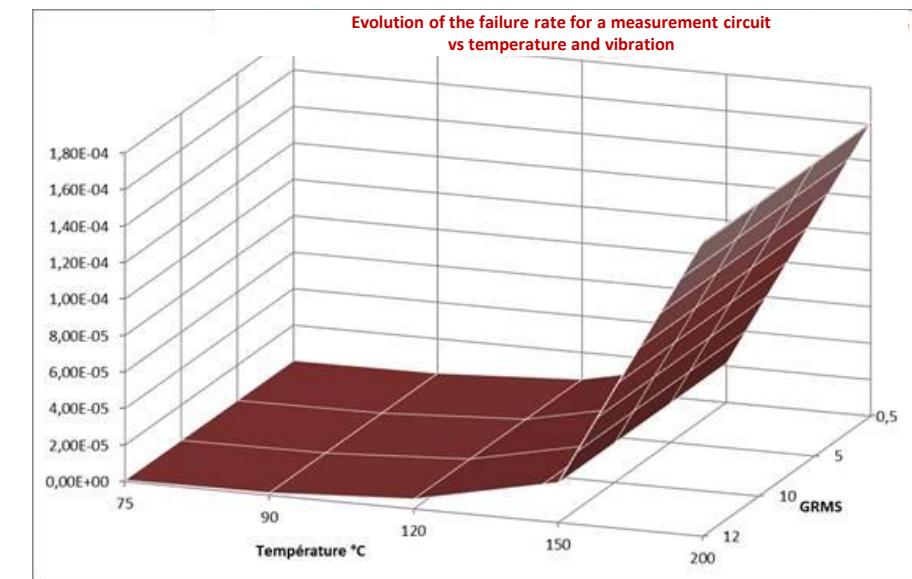
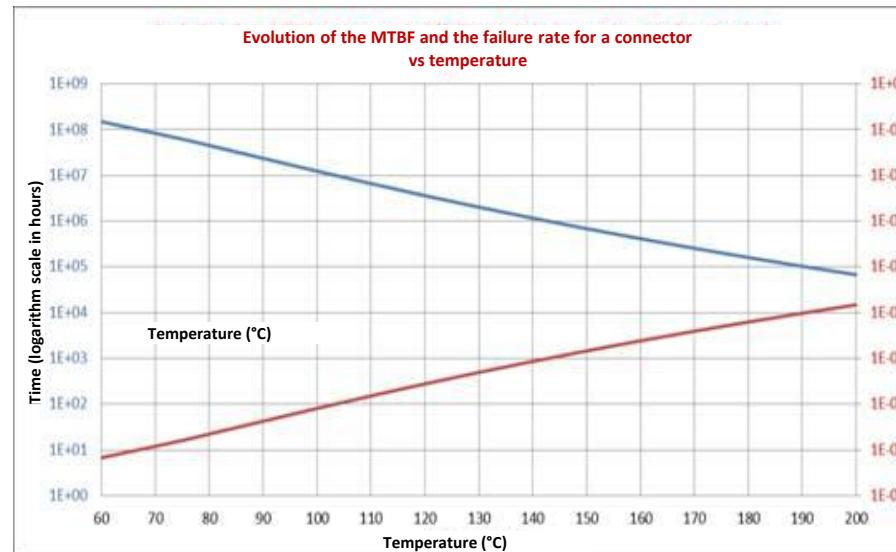
- Temperature
- Vibration

Vibration (Grms)	Temperature (°C)				
	75	90	120	150	200
0,5					
5					
12					

15 experiments have to be done



## Influence of the temperature



# *Reliability estimation (1)*

- Objective
  - Determine reliability laws (models) and their parameters from existing data (**tests or feedback**) to estimate experimental or operational reliability
- Description
  - Different laws (models) exist to express the reliability  $R(t)$ : **exponential, Weibull, normal, log-normal**  
...
  - The **exponential** distribution is characterized by the **failure rate**  $\lambda$  or the **mean time to failure MTTF**
  - The **Weibull** law is characterized by three factors: the **form factor**  $\beta$ , the **scale factor**  $\eta$ , and the **position factor**  $\gamma$
  - The **normal** and **log-normal** distributions are characterized by the **mean time to failure MTTF** or **MTBF** and the **standard deviation**  $\sigma$

# *Reliability estimation (2)*

- Process
  - Gathering of data (TTF or TBF) observed during tests or in use, selection and sorting in ascending chronological order
  - Non-parametric approach of the reliability law
    - Plotting of  $F(t_i)$  as a function of  $t_i$  (median ranks, mean ranks, Kaplan-Meier...)
    - Calculation or graphical evaluation of the parameters of the laws (functional papers)
    - Calculation of confidence intervals
- Area of relevance
  - Structured tests and feedback to provide consistent data
    - Defined failure modes
    - Controlled test conditions (temperature, vibration...)
    - Similarity of mission profiles
    - Time characterization

# *Reliability estimation (3)*

- Inputs
  - Reliability test results and conditions (TTF, TBF)
  - Events in operation over a period of time (failures)
- Outputs
  - Reliability models (laws, distributions) and their parameters
- Advantages
  - Data closest to reality
  - Simple calculations for the exponential distribution
  - Wealth of results
- Disadvantages
  - Limitations and assumptions for low data
  - Computational computations on Weibull parameter estimates
  - Need for consistent means for a rigorous and homogeneous gathering of data

## *Reliability estimation (4)*

## *Example of data*

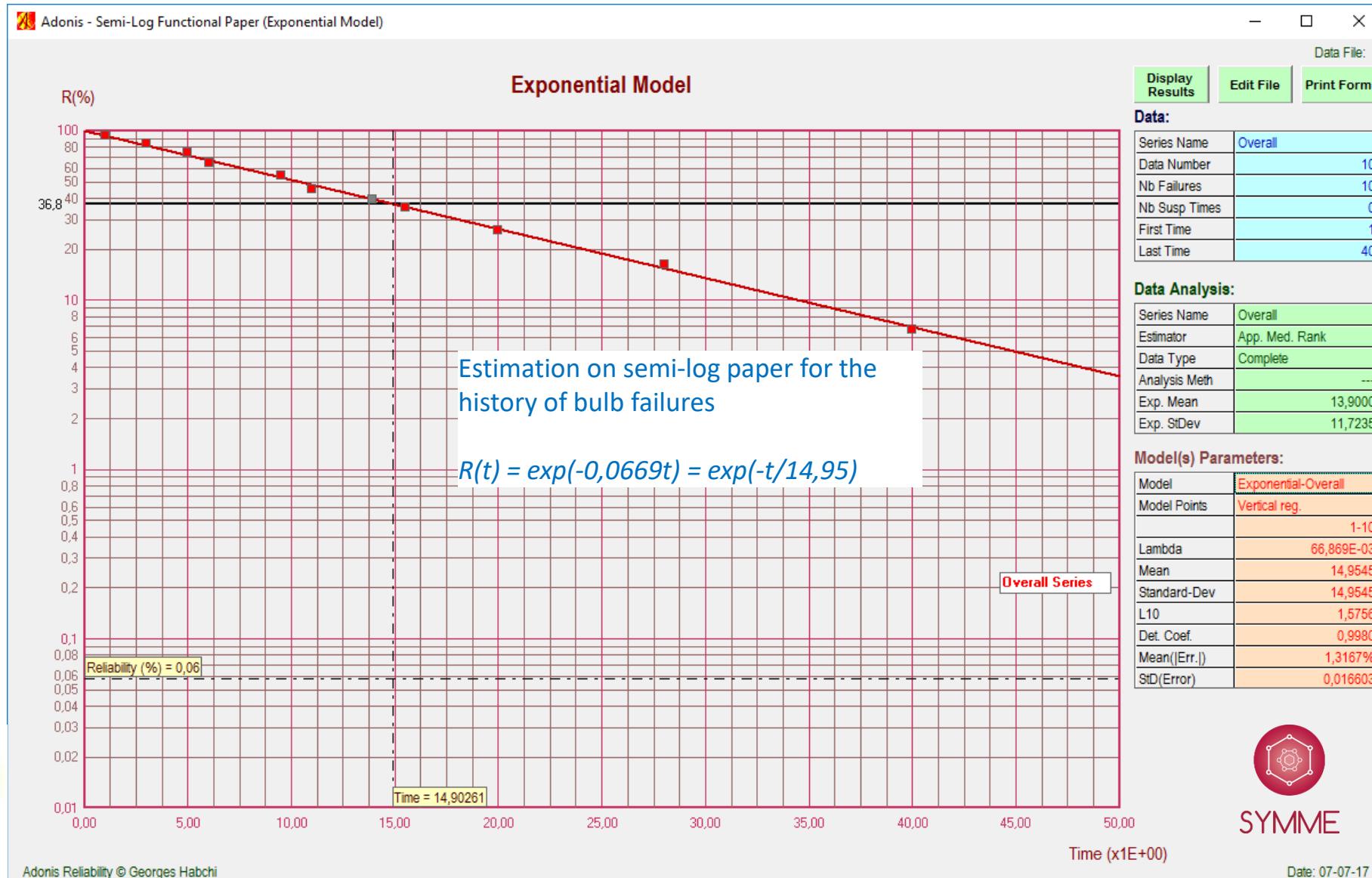
- Imagine that you have installed *10 identical light bulbs* (same brand, same power...) at the *same time* and that operate under *identical conditions*

- At 0 month, the 10 bulbs work
  - 1 month later, 1 bulb is out of service
  - 3 months later, another bulb is out of service
  - Etc.



# Reliability estimation (5)

Use of exponential distribution



# *Reliability estimation (6)*

*Example of data*

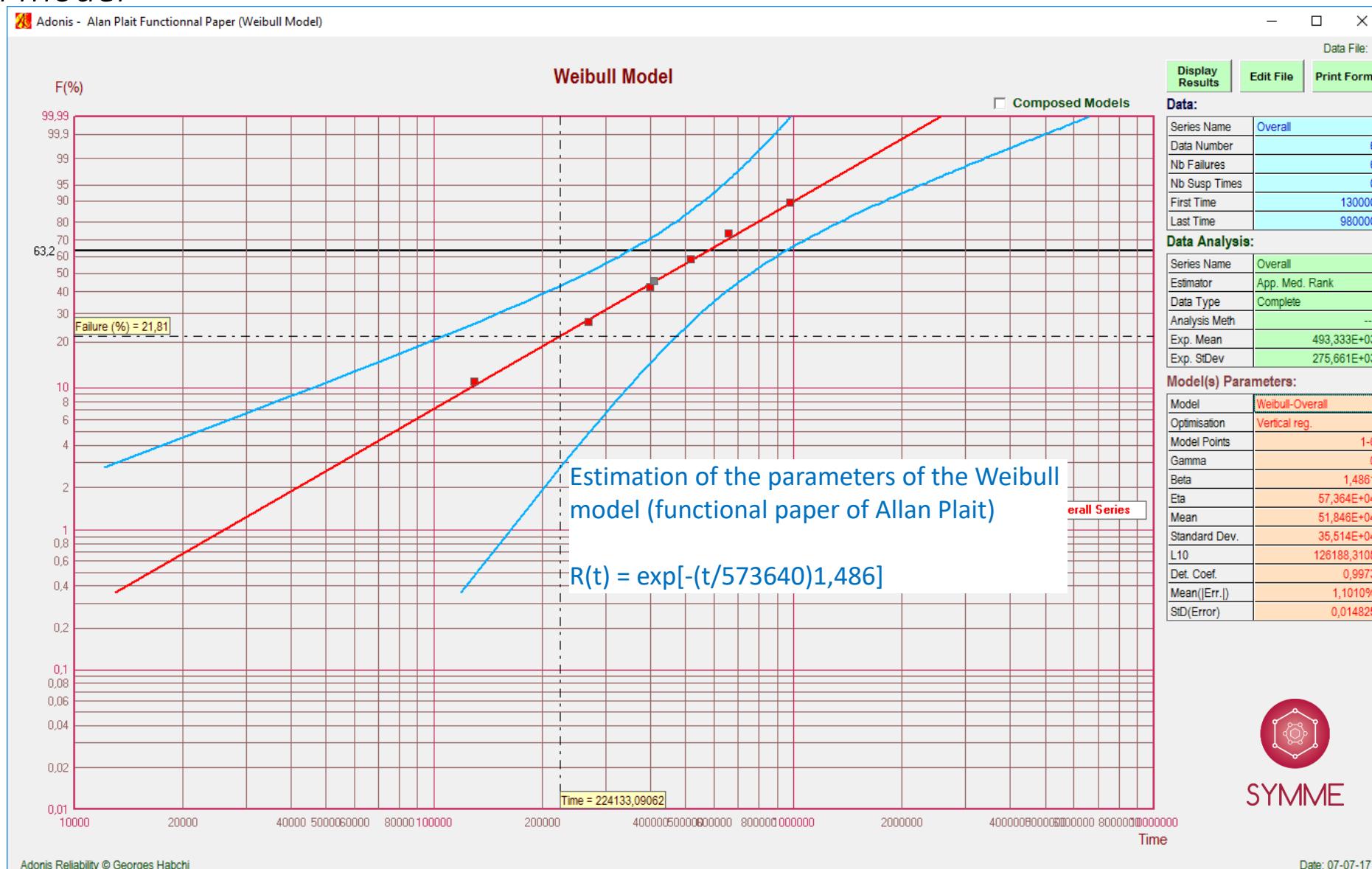
- A life test was performed on a **lot of 6 loaded bearings under specific conditions** and the following results were recorded



Bearing N°#	1	2	3	4	5	6
Number of cycles at break	400 000	130 000	980 000	270 000	660 000	520 000

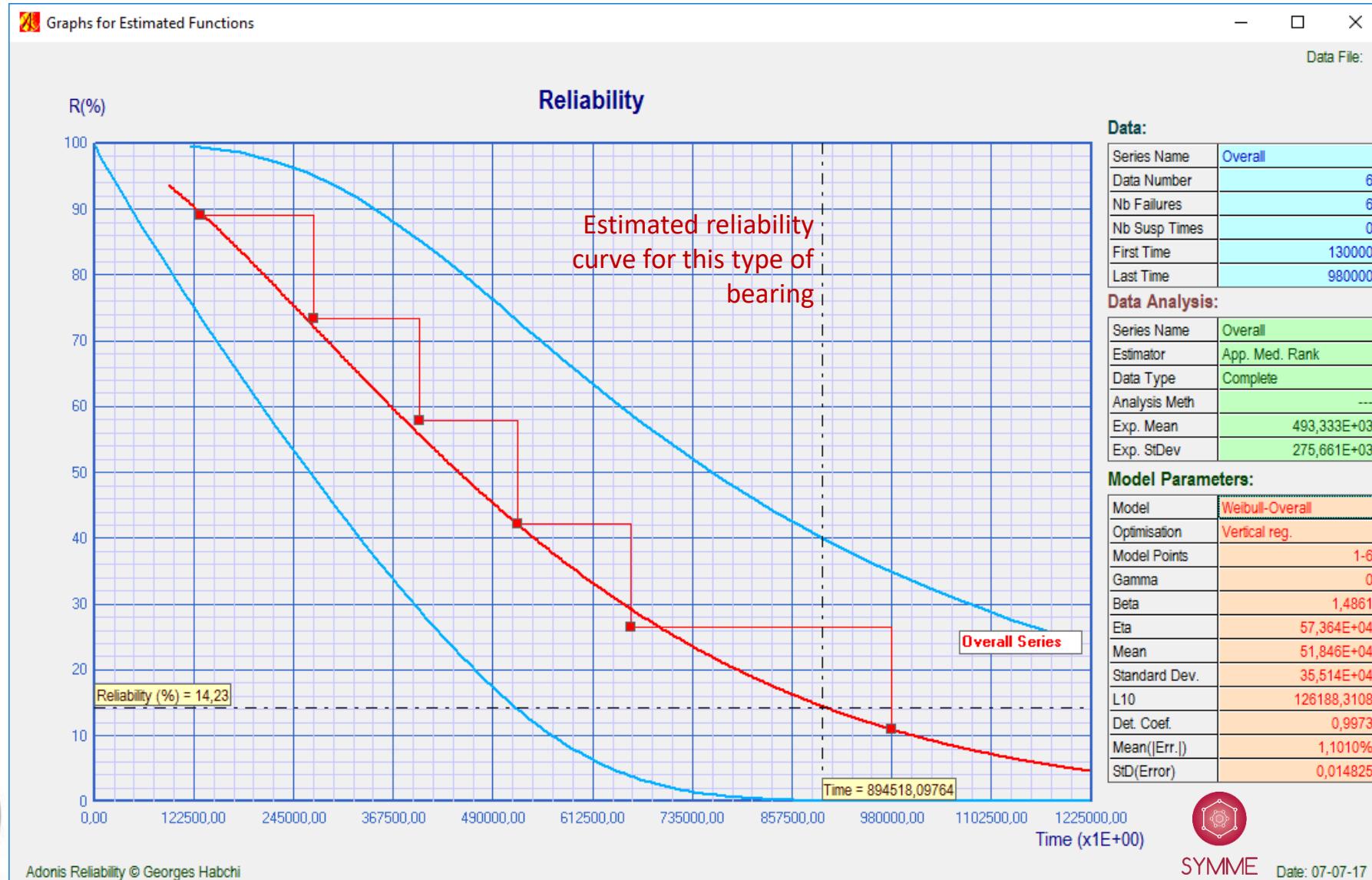
# Reliability estimation (7)

## Use of Weibull model

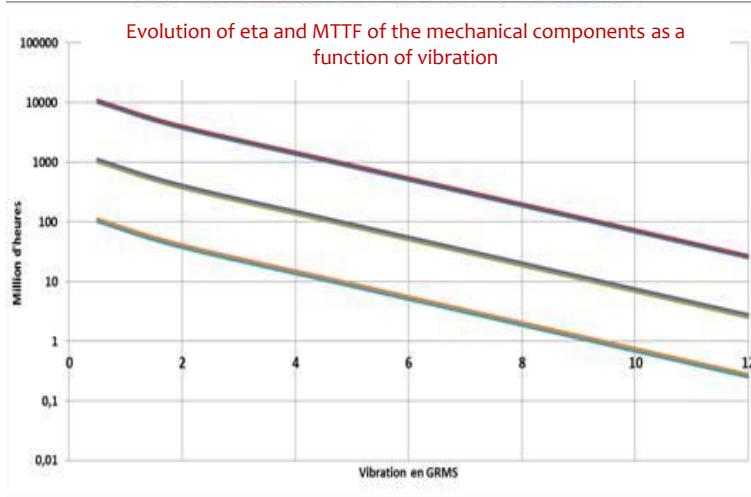
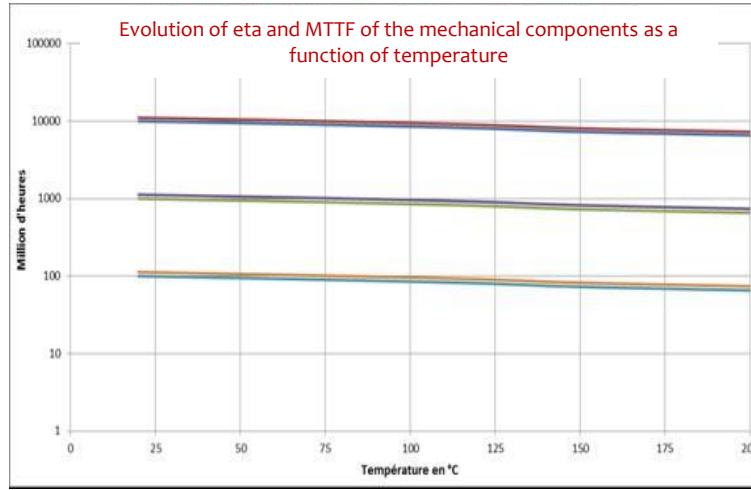


# Reliability estimation (8)

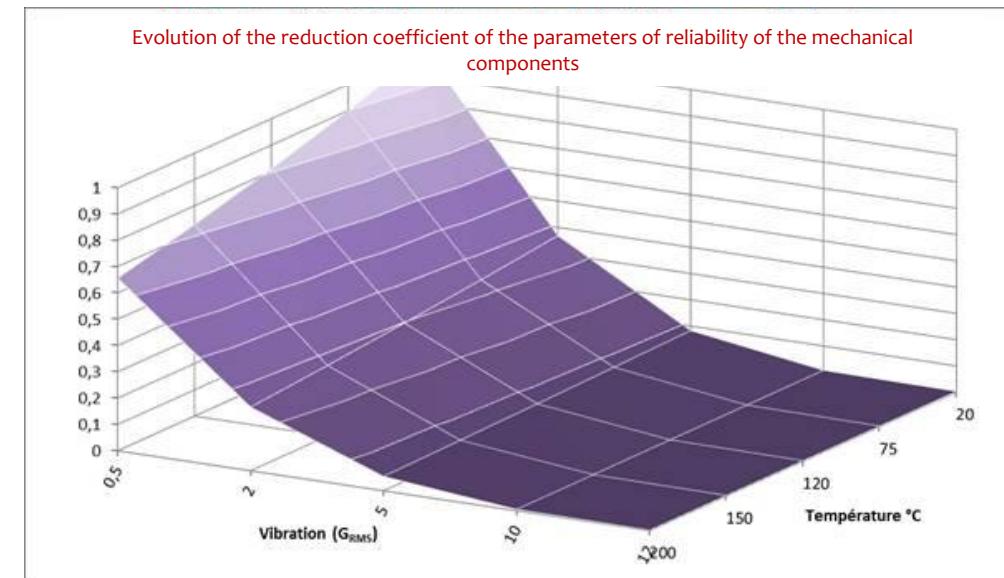
## Use of Weibull model



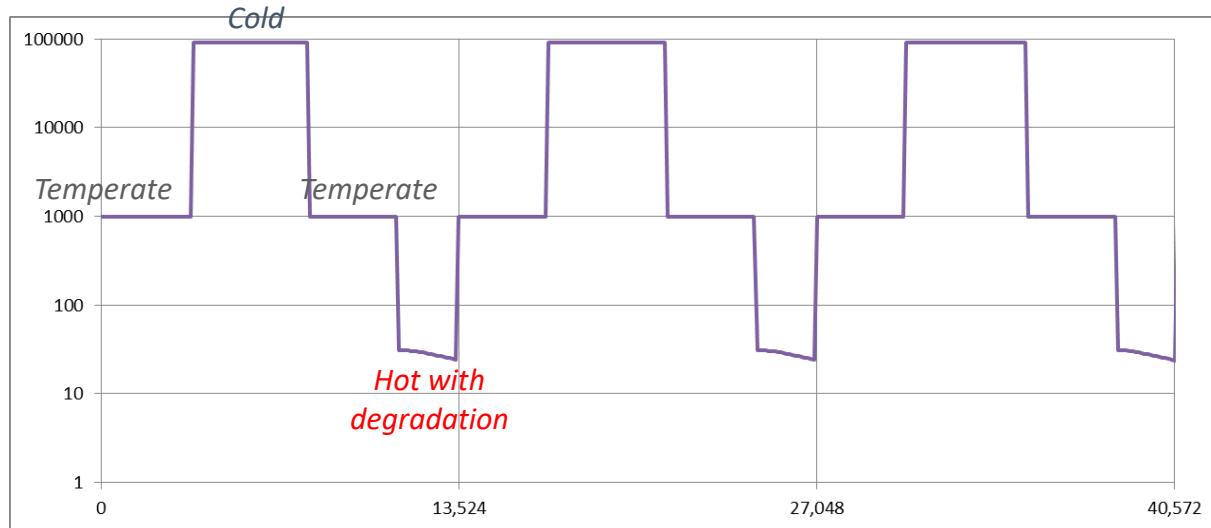
# Influence of the environment on the degradation of mechanical components



- Law and values of the parameters chosen according to the experience of the manufacturer in the field of reliability (tests, feedback)
- Proposed evolution of parameters as a function of temperature and vibration



# Influence of the mission profile on the parameters of reliability in the presence of interaction

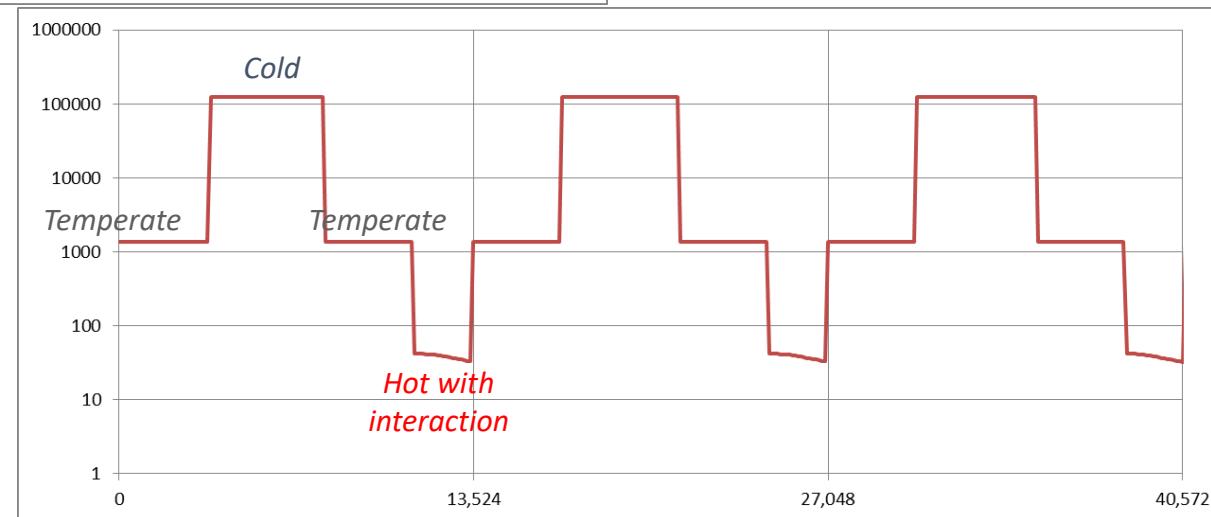


Evolution of the scale parameter  $\eta$  of the bearing according to:

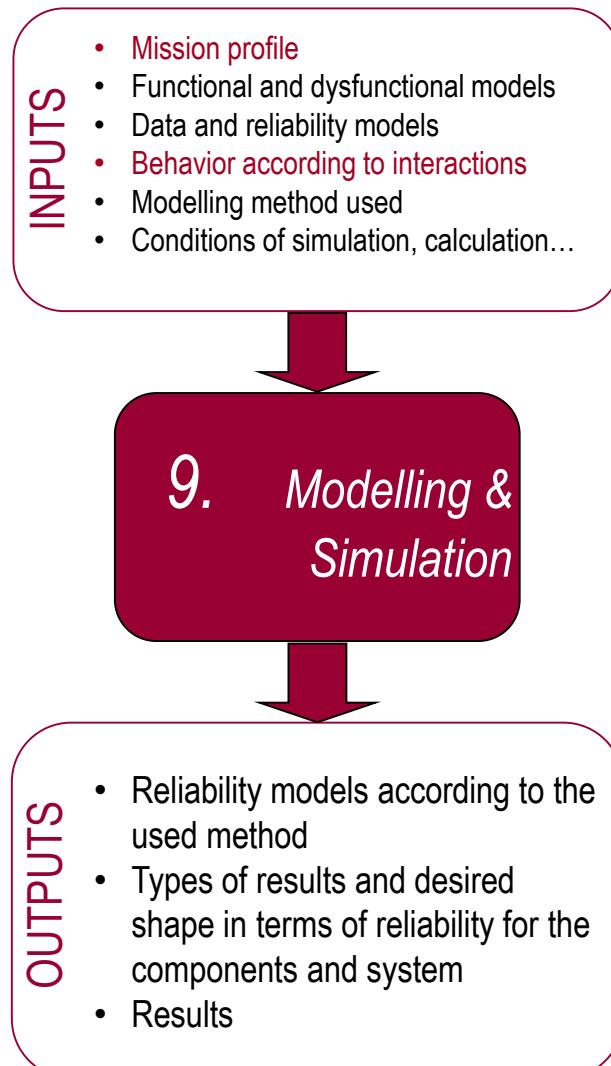
- Mission profile phases
- Degradation in the “hot” phase

Evolution of the MTTF of the coil according to:

- Mission profile phases
- Interaction with the bearing in the “hot” phase



# 9. Modelling and Simulation

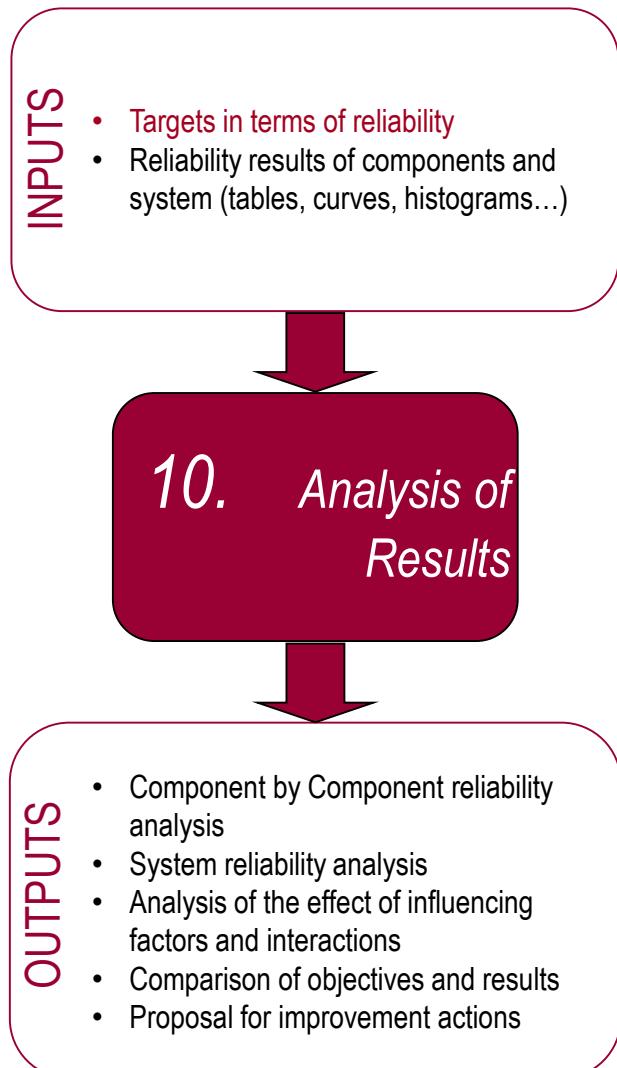


Implements the reliability models according to the chosen method, taking into account inputs and outputs and provides reliability results

Two methods are used:

1. **Petri nets** used for behavioral modeling of the different states of the system and **Monte Carlo** simulation for the quantification of the results of reliability
2. **Reliability Diagrams** used for block modeling of components and an analytical calculation of reliability

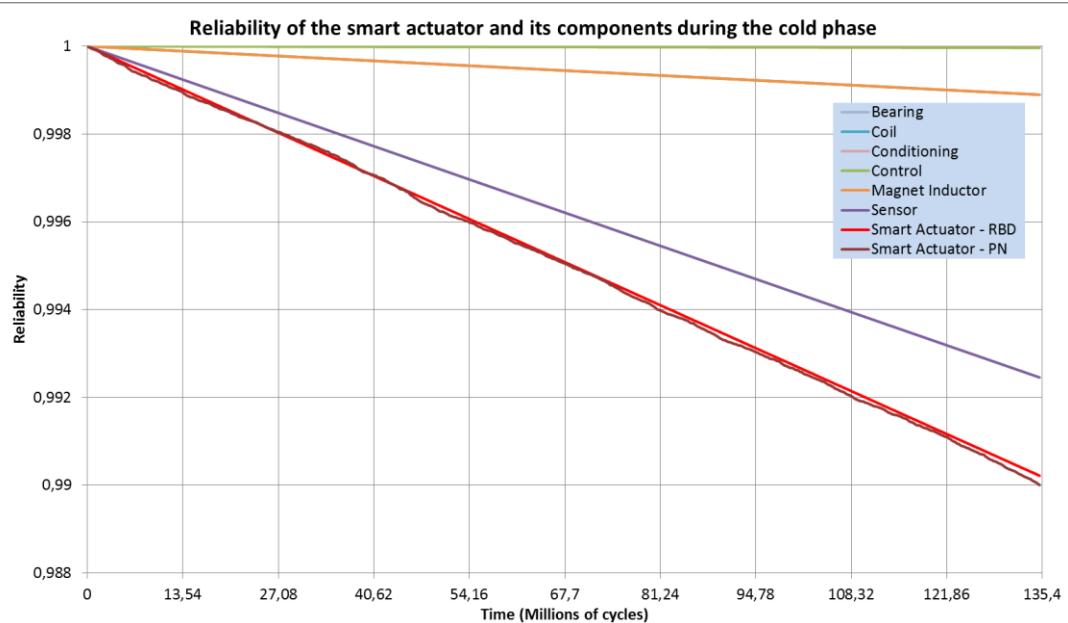
# 10. Analysis of Results



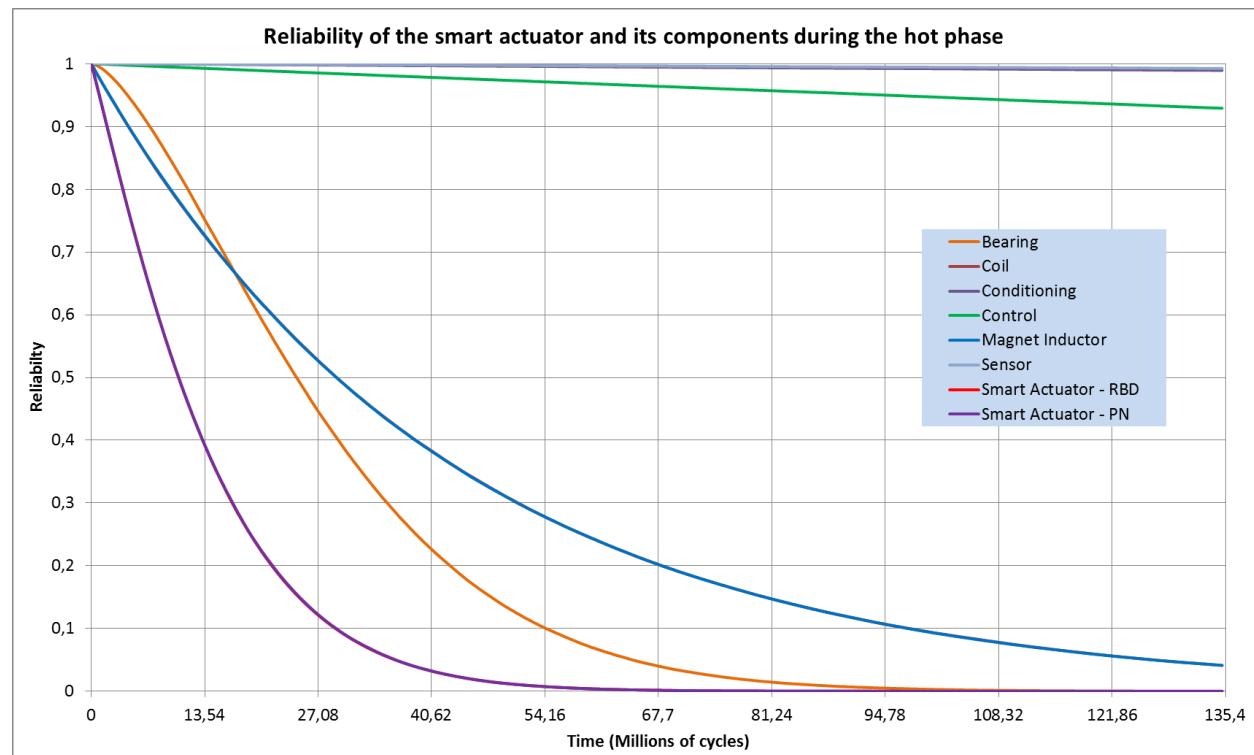
1. Evaluates the components and system reliability against targets
2. Evaluates the effect of influencing factors and interactions
3. Targets Critical Components
4. Proposes conclusions and improvement actions

# Results of reliability

Reliability of the smart actuator and components phase/phase



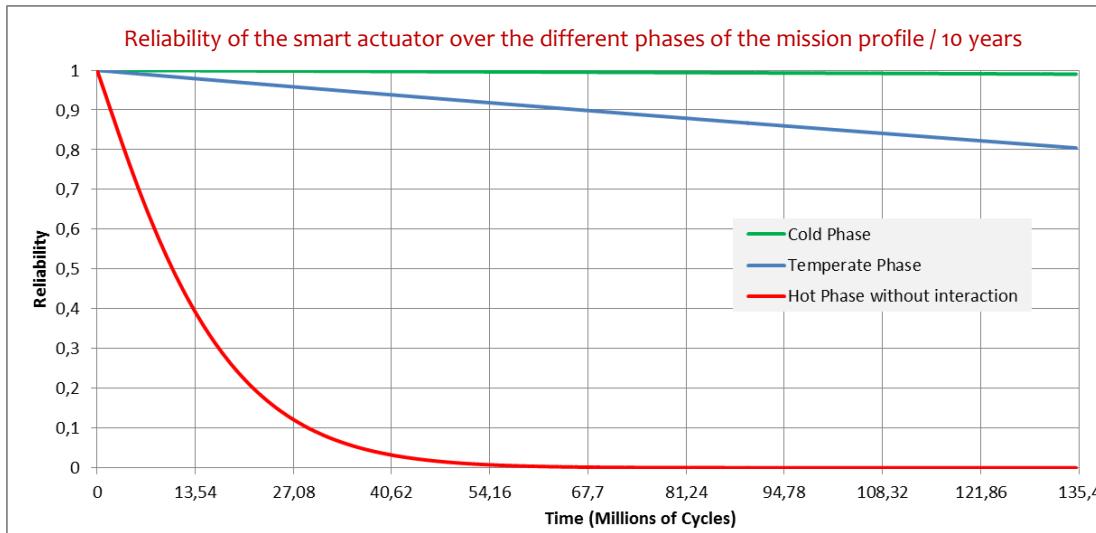
Reliability of the smart actuator and its components for the "cold" phase without bearing/coil interaction



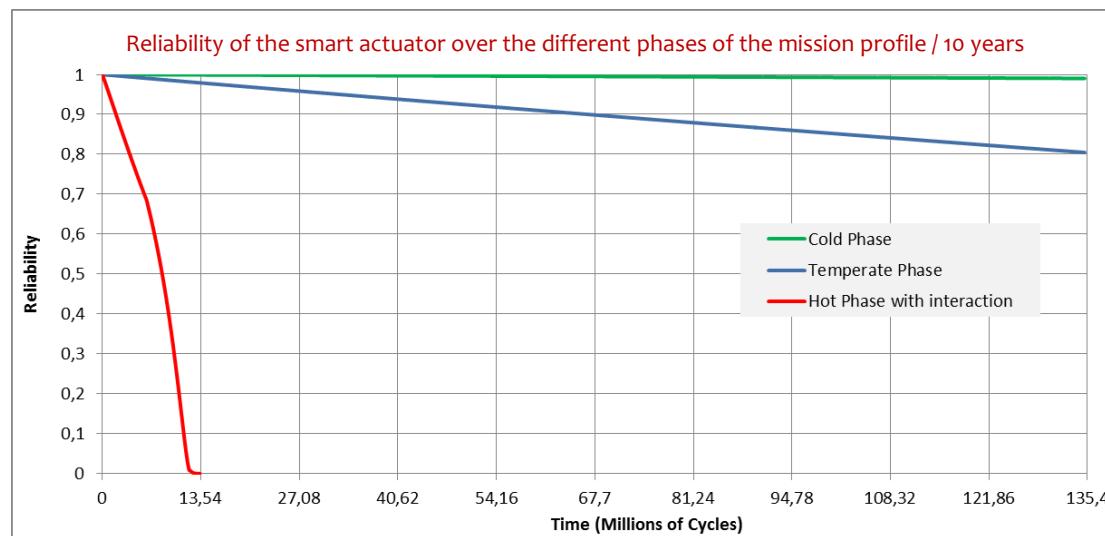
Reliability of the smart actuator and its components for the "hot" phase without bearing/coil interaction

# Results of reliability

Reliability of the smart actuator without and with interaction (phase/phase)



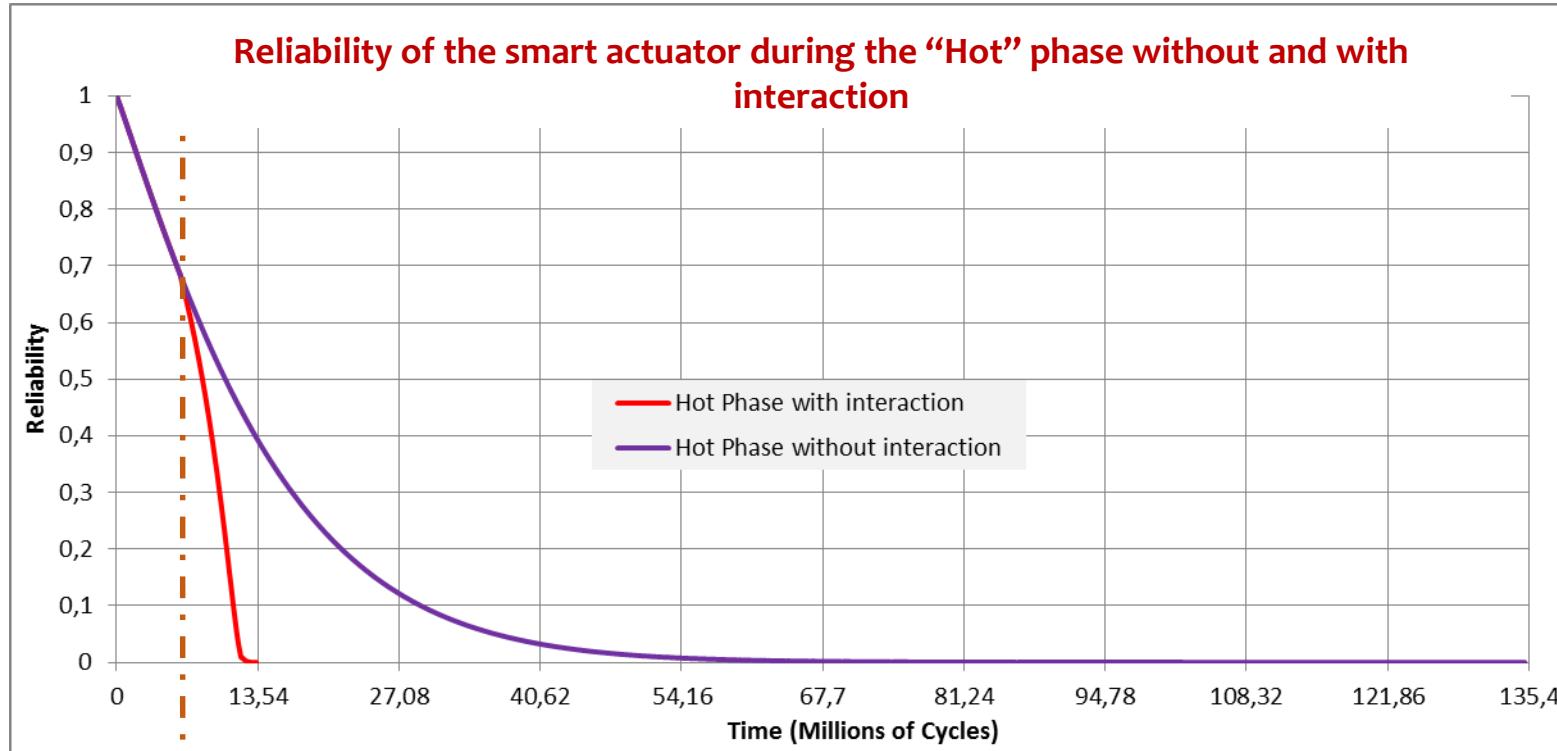
Reliability of the smart actuator phase/phase  
without bearing/coil interaction



Reliability of the smart actuator phase/phase  
with bearing/coil interaction

# Results of reliability

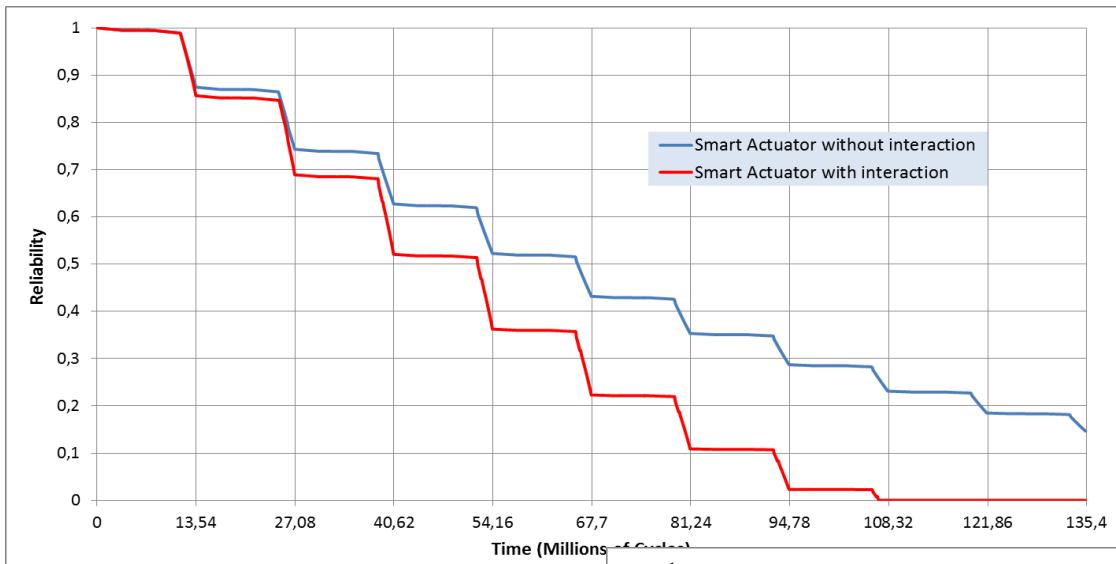
Reliability of the smart actuator without and with interaction during the “Hot” phase



Influence of the bearing / coil interaction  
from 6 million cycles

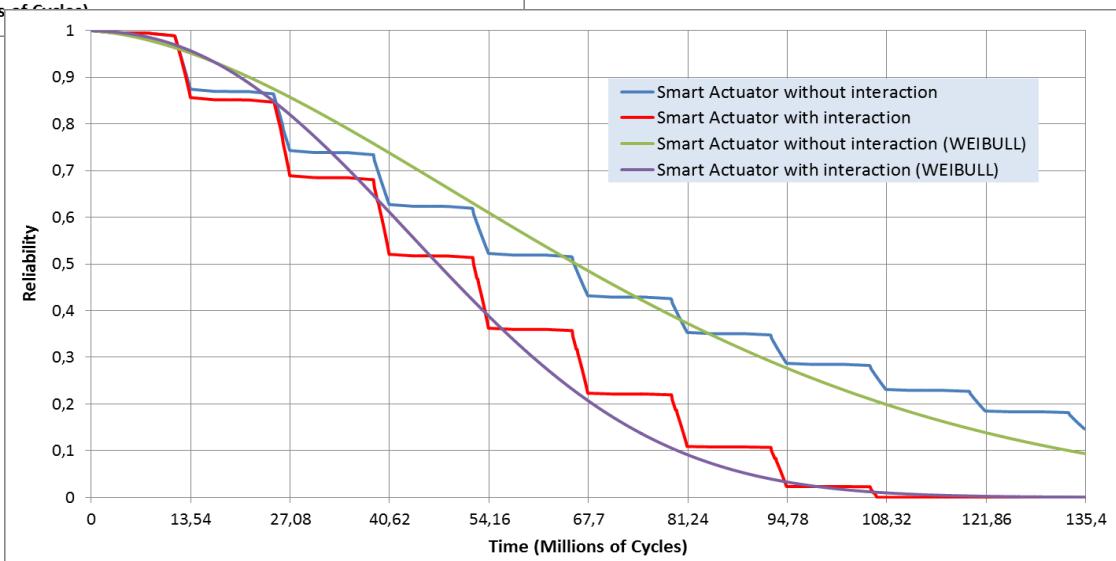
# Results of reliability

Reliability of the smart actuator according to the mission profile



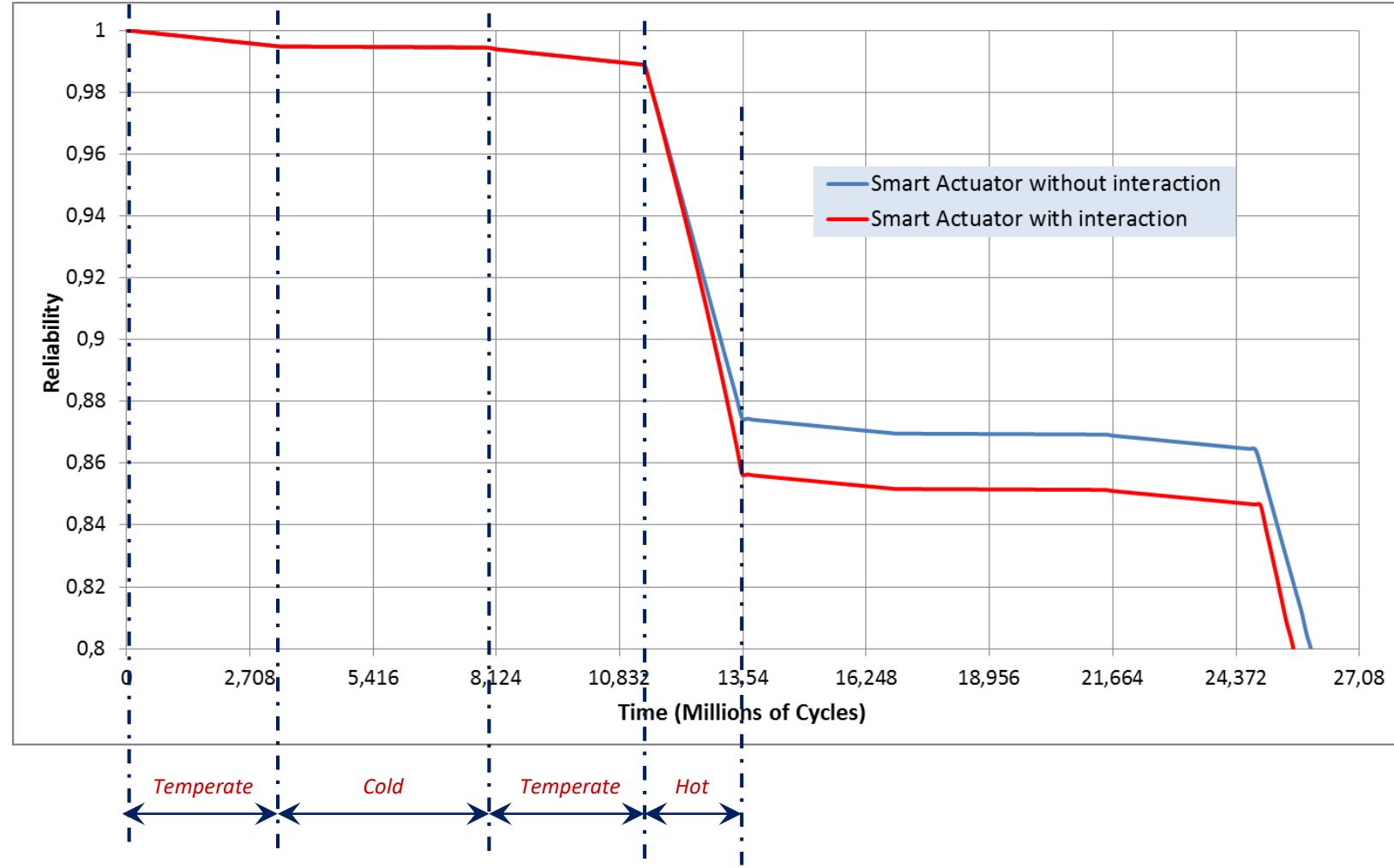
Reliability of the smart actuator **without** and **with bearing/coil interaction**

Search for reliability models **without** and **with bearing/coil interaction**



# Results of reliability

Reliability of the smart actuator according to the mission profile (one-year zoom)

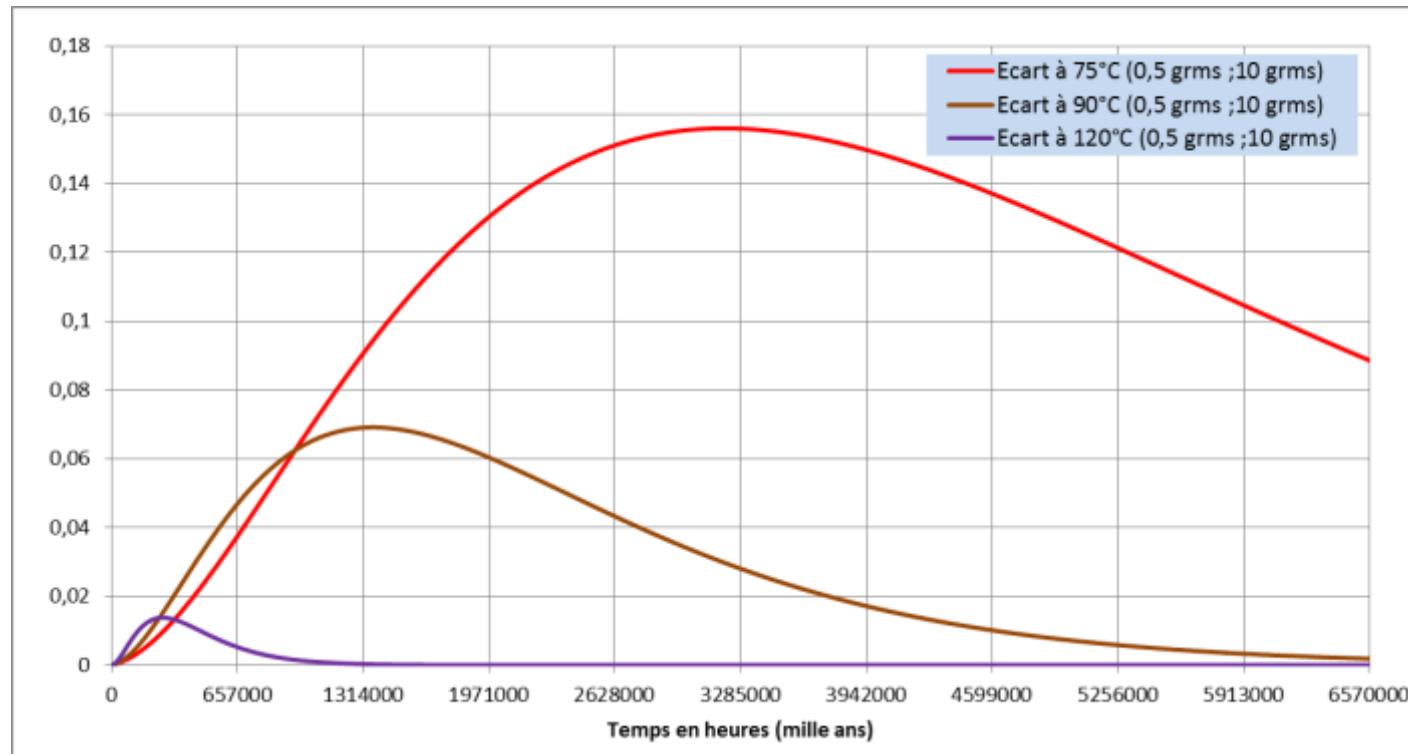


# *Results of reliability*

*Reliability of the electronic measuring circuit*



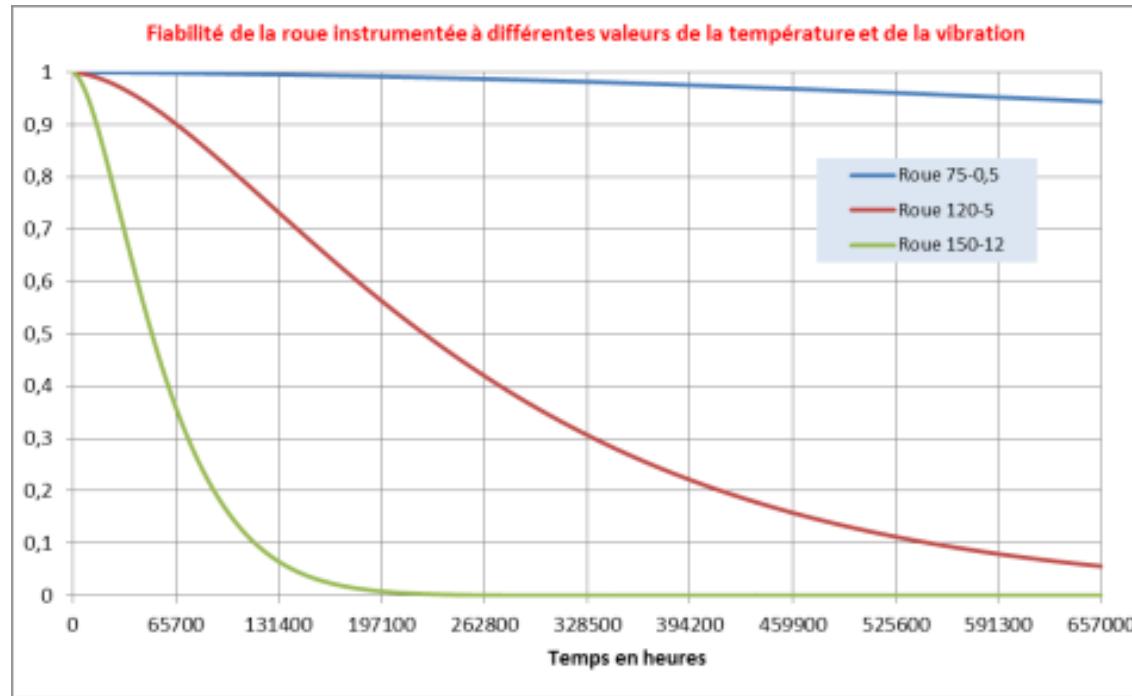
## **Evolution of the deviation of reliability as a function of temperature and vibration**



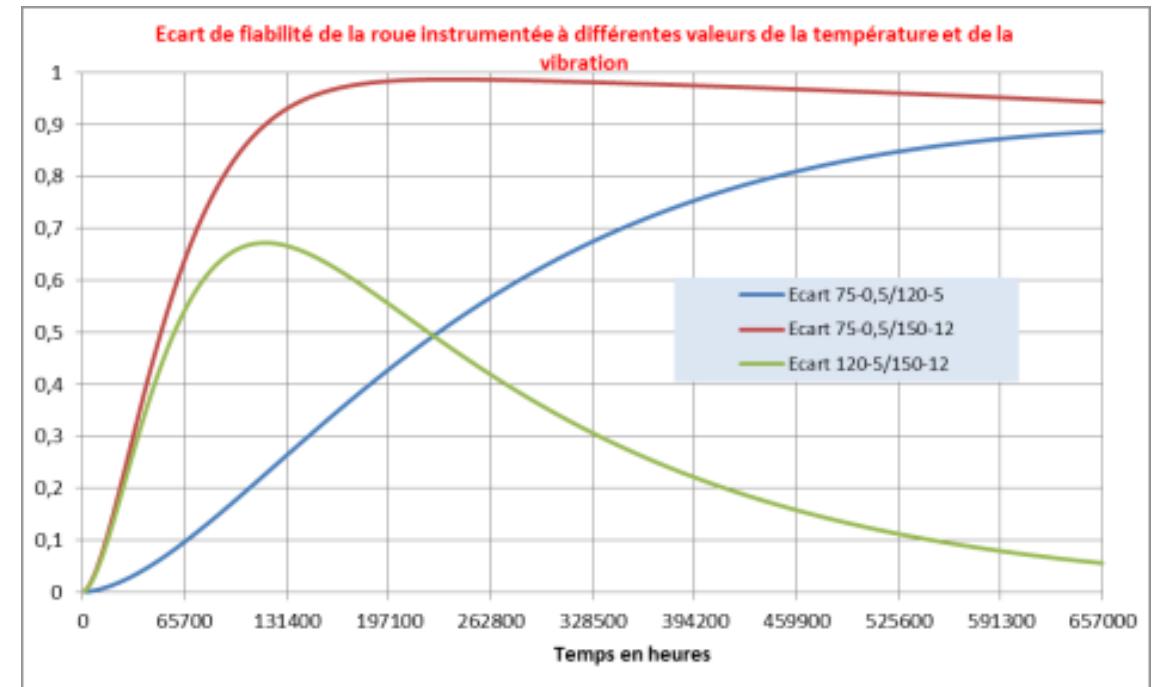
# Results of reliability

Reliability of the instrumented wheel bearing

NTN SNR



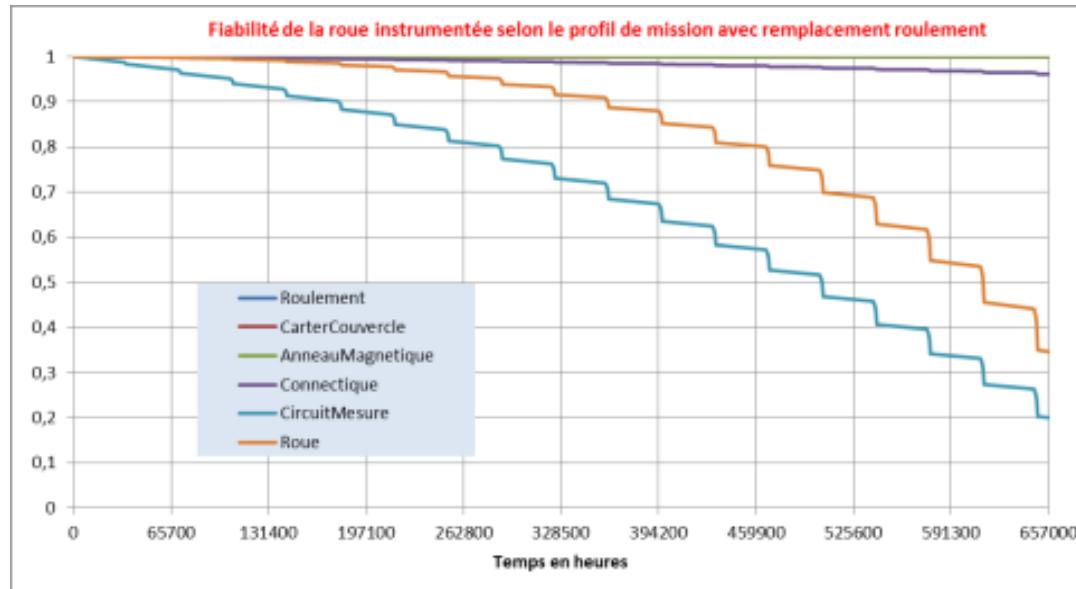
Reliability of the instrumented wheel bearing as a function of the **influence factors** (temperature, vibration)



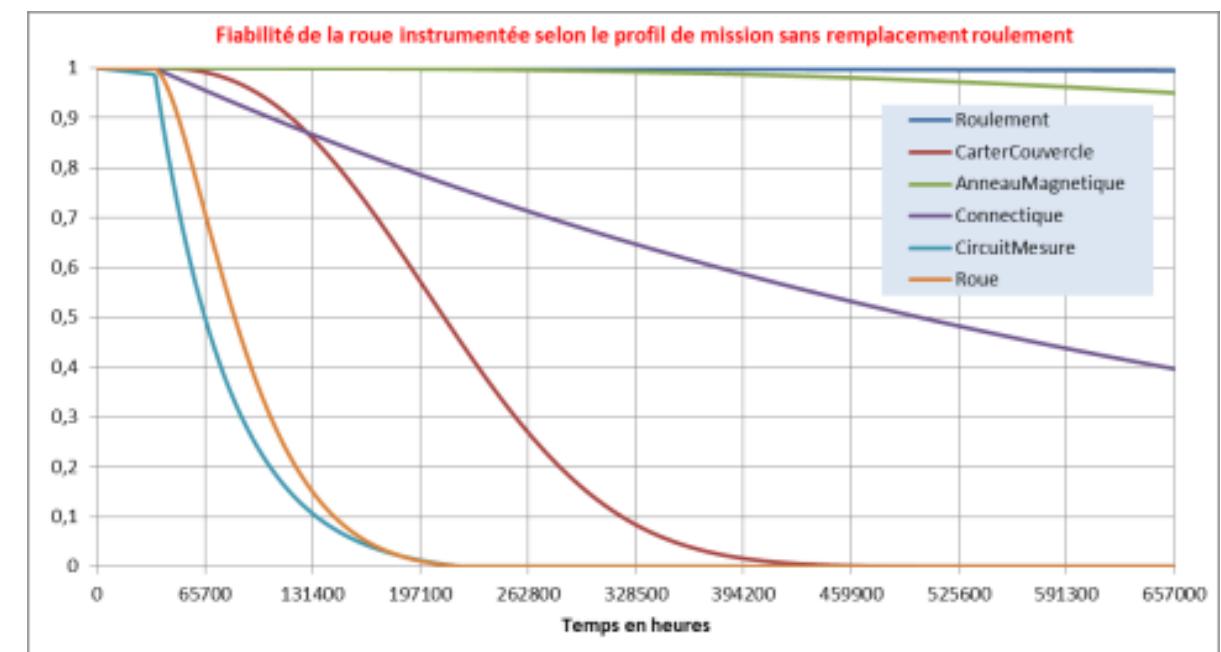
**Deviation of reliability** of the instrumented wheel bearing as a function of temperature and vibration

# Results of reliability

Reliability of the instrumented wheel bearing



Reliability of the instrumented wheel bearing and its components **with bearing replacement due to flaking**

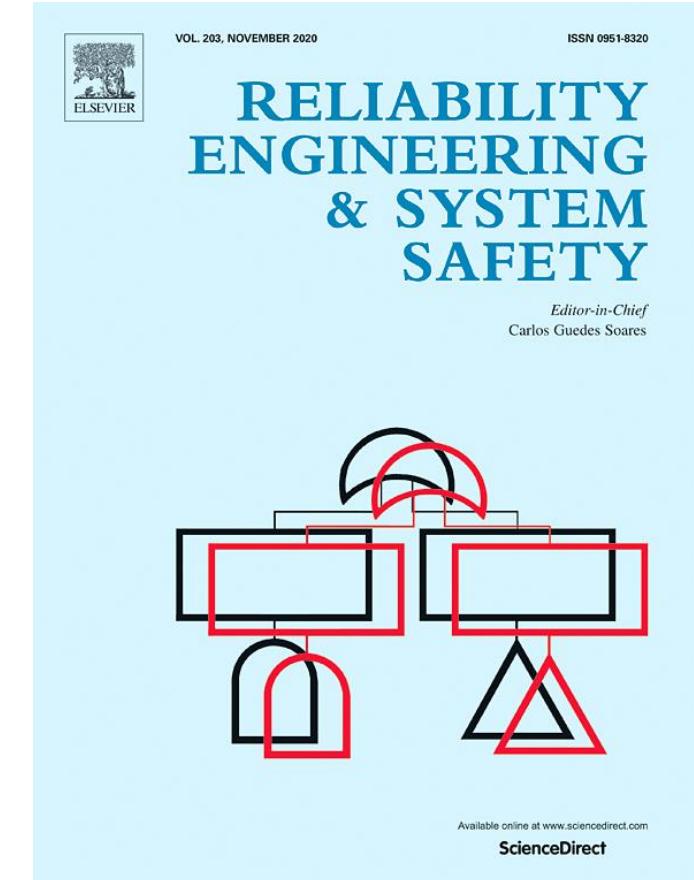
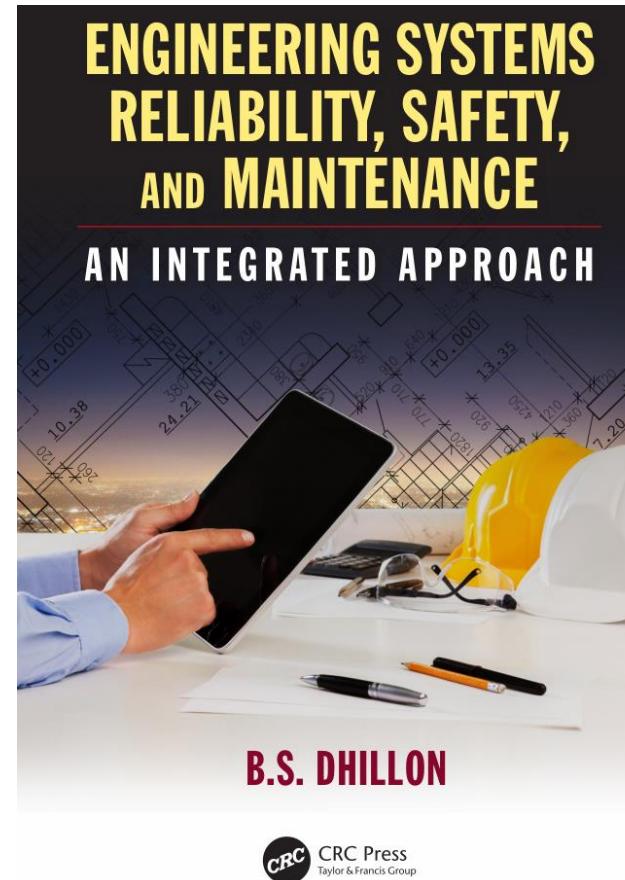
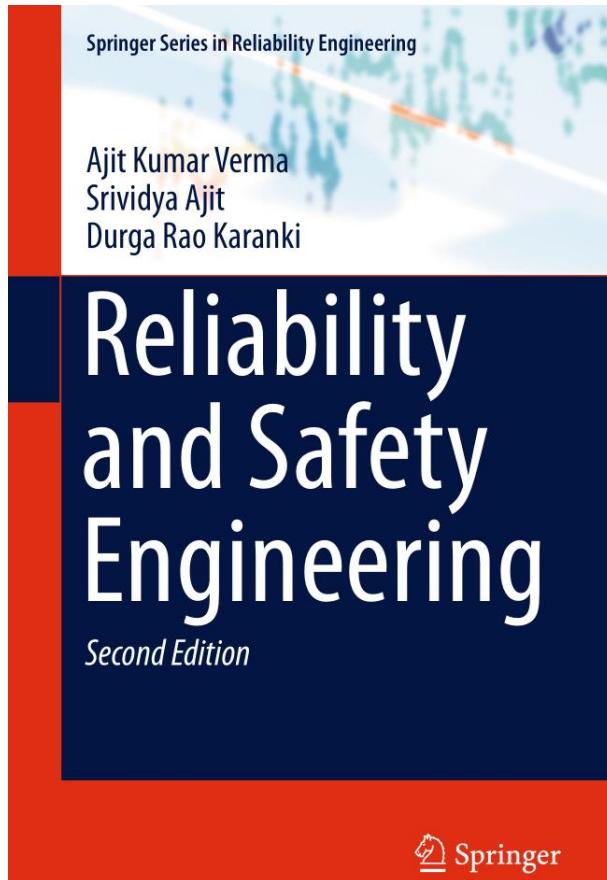


Reliability of the instrumented wheel bearing and its components **without bearing replacement due to flaking**

# Conclusions

- Development of an approach to assess the predictive reliability of mechatronic systems
  - Structured and based on **the V-cycle**
  - Both **qualitative and quantitative**
  - Taking into account the characteristics of these systems: **dynamic, hybrid, reconfigurable, interactive (interdependent)**
  - Enabling to assess the **overall reliability** of the system in its multi-technology definition
  - Taking into account a **mission profile, influence factors** and **collateral and functional interactions** (interdependencies)
  - Allowing to evolve certain classical methods (FMEA: analysis with **classification of the modes of failure**, taking into account the **collateral interactions**, DF: taking into account the **mission profile** and the **interactions**)
  - Consolidated and validated on industrial **mechatronic products / systems**

## Relevant books



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SYMME

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